



INVESTOR PRESENTATION

May 2026

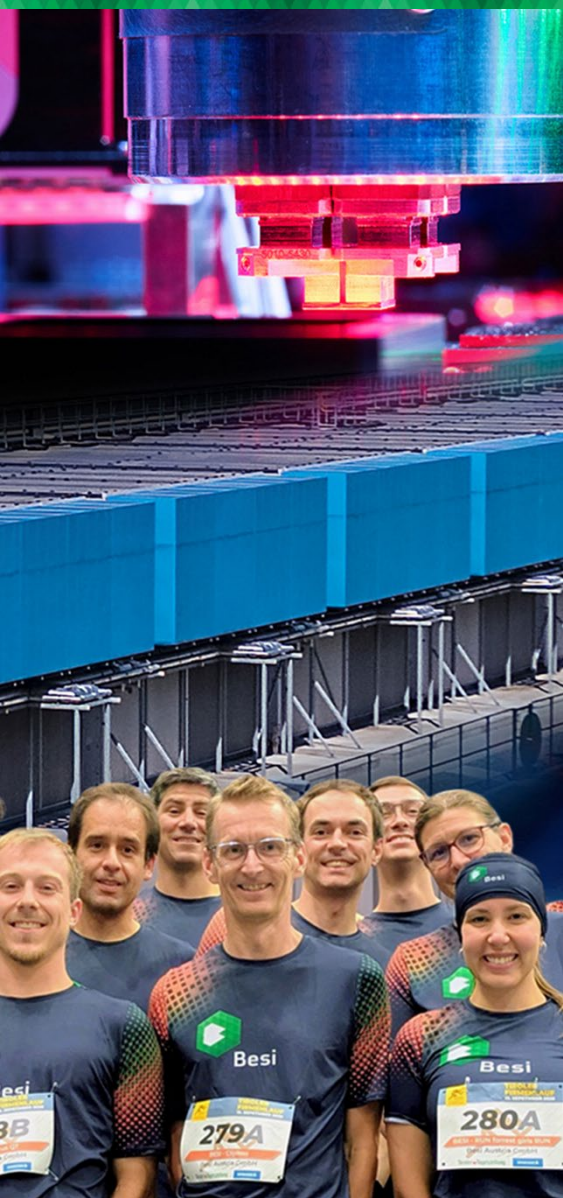
Safe Harbor Statement



This presentation contains statements about management's future expectations, plans and prospects of our business that constitute forward-looking statements, which are found in various places throughout the presentation, including, but not limited to, statements relating to expectations of orders, net sales, product shipments, expenses, timing of purchases of assembly equipment by customers, gross margins, operating results and capital expenditures. The use of words such as “anticipate”, “estimate”, “expect”, “can”, “intend”, “believes”, “may”, “plan”, “predict”, “project”, “forecast”, “will”, “would”, and similar expressions are intended to identify forward-looking statements, although not all forward-looking statements contain these identifying words. In addition, the financial guidance set forth under the heading “Outlook” contains forward-looking statements. While these forward-looking statements represent our judgments and expectations concerning the development of our business, a number of risks, uncertainties and other important factors could cause actual developments and results to differ materially from those contained in forward-looking statements, including any inability to maintain continued demand for our products; failure of anticipated orders to materialize or postponement or cancellation of orders, generally without charges; the volatility in the demand for semiconductors and our products and services; the adverse impacts on the global economy, financial markets, global supply chains and our operations as well as those of our customers and suppliers arising from the COVID-19 pandemic ; failure to develop new and enhanced products and introduce them at competitive price levels; failure to adequately manage costs and expenses in line with revenue; loss of significant customers, including through industry consolidation or the emergence of industry alliances; lengthening of the sales cycle; acts of terrorism and violence; disruption or failure of our information technology systems; consolidation activity and industry alliances in the semiconductor industry that may result in further increased customer concentration, inability to forecast demand and inventory levels for our products; the integrity of product pricing and protection of our intellectual property in foreign jurisdictions; risks, such as changes in trade regulations, conflict minerals regulations, currency fluctuations, political instability and war, associated with substantial foreign customers, suppliers and foreign manufacturing operations, particularly to the extent occurring in the Asia Pacific region where we have a substantial portion of our production facilities; potential instability in foreign capital markets; the risk of failure to successfully manage our diverse operations; any inability to attract and retain skilled personnel, including as a result of restrictions on immigration, travel or the availability of visas for skilled technology workers; and the other risks detailed in the Risk Management section of our Annual Report. We expressly disclaim any obligation to update or alter these forward-looking statements for revisions or changes whether as a result of new information, future events or otherwise after the date of this release.

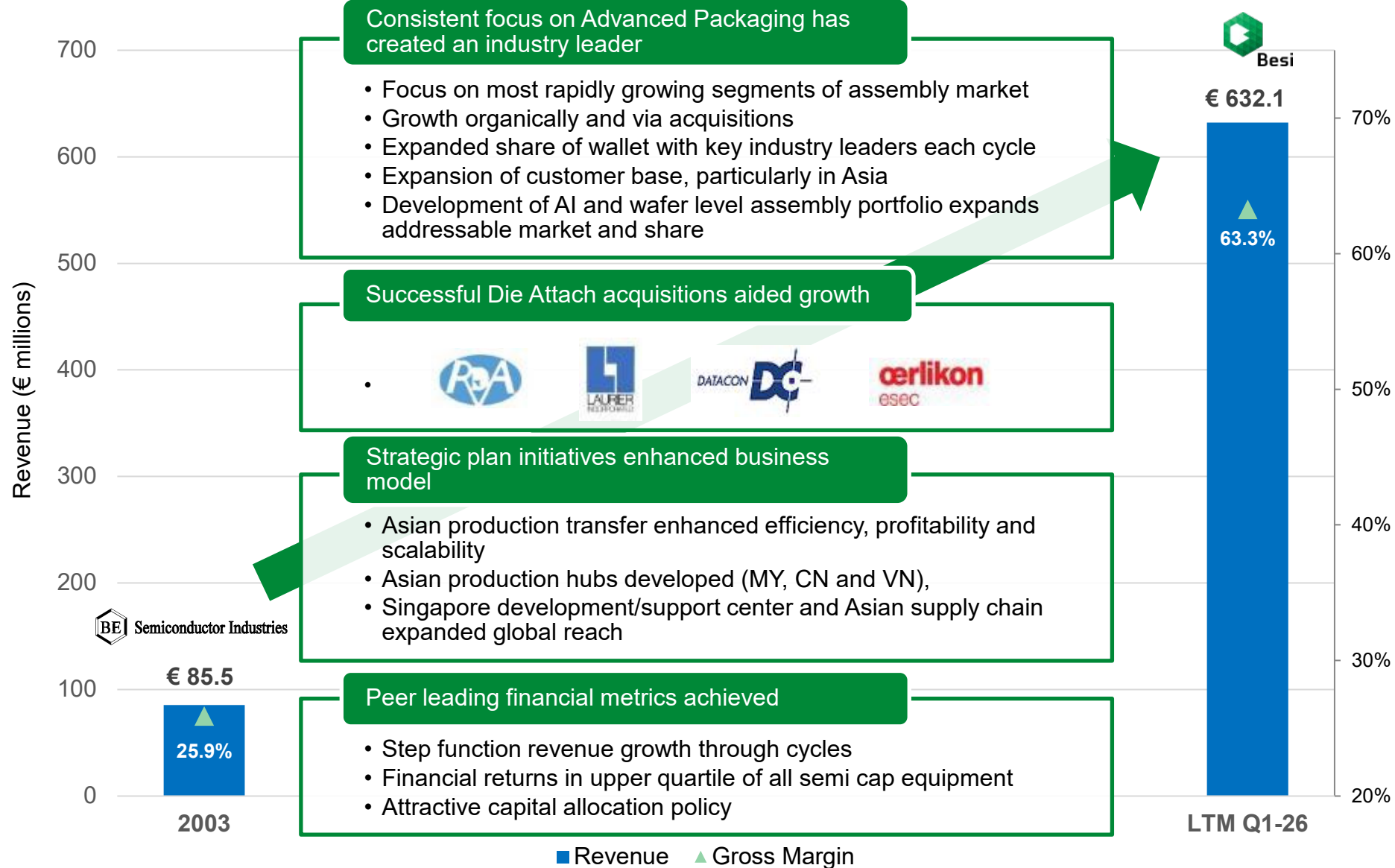
In addition, the United States and other countries have recently levied tariffs and taxes on certain goods and could significantly increase or impose new tariffs on a broad array of goods. They have imposed, and may continue to impose, new trade restrictions and export regulations. Increased or new tariffs and additional taxes, including any retaliatory measures, trade restrictions and export regulations, could negatively impact end-user demand and customer investment in semiconductor equipment, increase Besi's supply chain complexity and manufacturing costs, decrease margins, reduce the competitiveness of our products or restrict our ability to sell products, provide services or purchase necessary equipment and supplies. Any or all of the foregoing factor could have a material and adverse effect on our business, results of operations or financial condition. In addition, investors should consider those additional risk factors set forth in Besi's annual report for the year ended December 31, 2025 and other key factors that could adversely affect our businesses and financial performance contained in our filings and reports, including our statutory consolidated statements. We expressly disclaim any obligation to update or alter our forward-looking statements whether as a result of new information, future events or otherwise.

- I. Company Overview
- II. Market Overview
- III. End-User Market Trends
- IV. Financial Update and Summary



I. COMPANY OVERVIEW

Company History





- ✓ Strategic plan updated to include new revenue and cost initiatives. Increased revenue target from € 1 billion+++ to € 1.5 - € 1.9 billion
- ✓ Continued progress on wafer level assembly agenda:
 - ✓ Hybrid bonding adoption grew to 150+ cumulative orders and 18 customers
 - ✓ New use cases identified for ASIC devices and co packaged optics
 - ✓ New hybrid prototype system completed with 50nm accuracy and increased throughput
 - ✓ First integrated hybrid bonding production lines installed
 - ✓ TC Next adoption expanded to 5 customers and multiple end markets
- ✓ Expansion of cleanroom capacity and Asian support to aid advanced packaging growth
- ✓ New products introduced for next gen AI applications and next market upcycle
- ✓ Substantial progress achieved versus 2026 sustainability targets

Capital Allocation

Attractive capital allocation program

€ 2.4 billion of dividends and share repurchases since 2011*

Represents ~33% of total revenue

Strategic/Financial

Disciplined execution has created leader in advanced packaging

Best in class financial metrics

Superior through cycle financial performance versus peers

Shareholder Return

Superior Total Returns:**
140% (3 year)
194% (5 year)
2,143% (10 year)

Consistent TSR outperformance versus peers

Upper quartile ranking for all semi-equipment companies

* Includes dividend for fiscal 2025

** Through March 31, 2026

Market Positioning: From Processed Wafer to Assembled Chip

Total Semiconductor Manufacturing Equipment 2025 (E): \$ 136B

Front end: \$ 118.9B
(87%)

Assembly: \$ 5.2B
(4%)

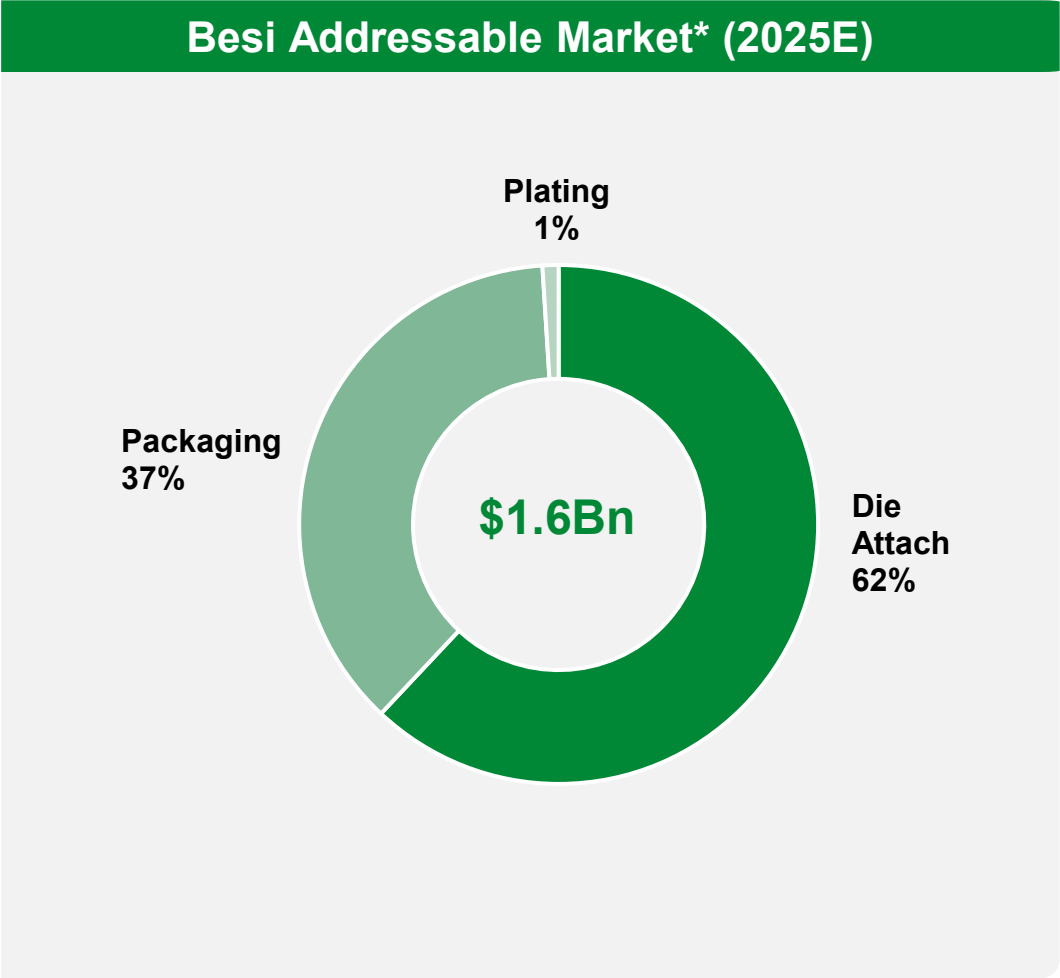
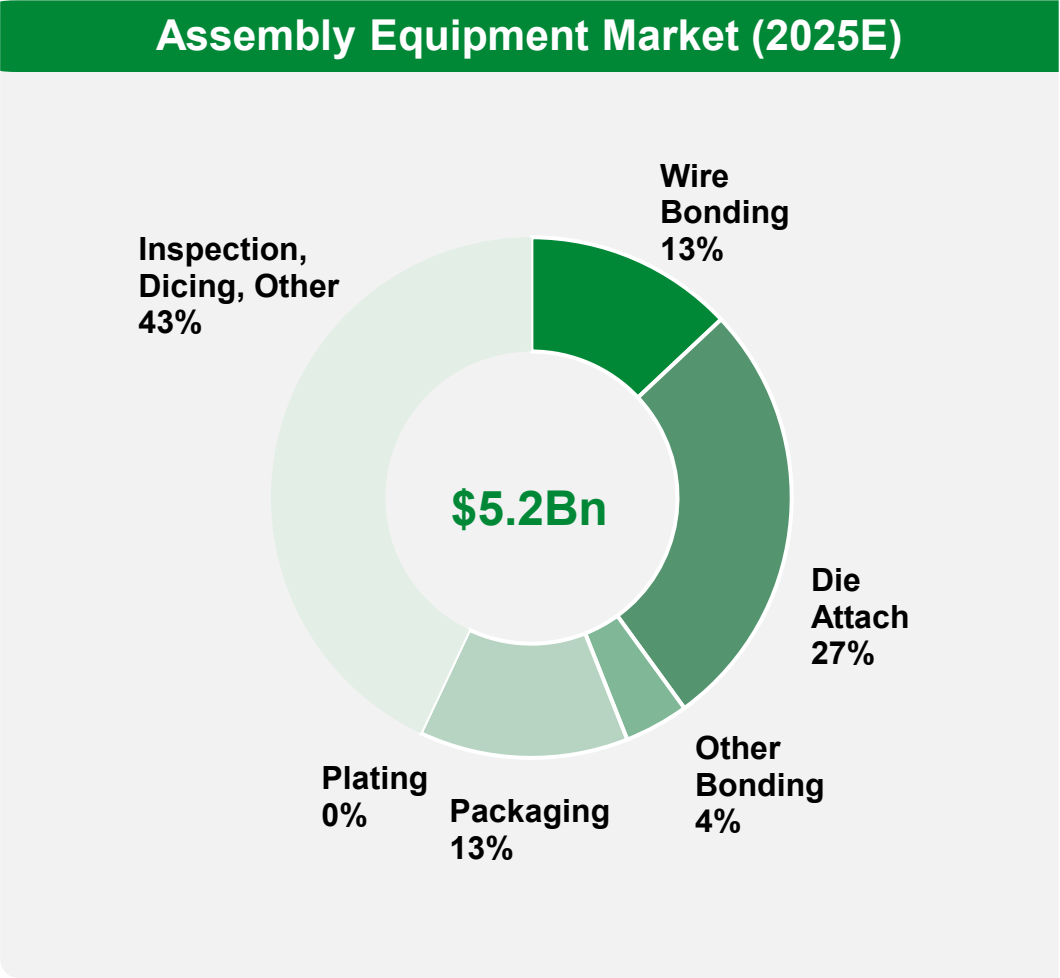
Test: \$ 12.0B
(9%)

Besi focus

Assembly Process

Dicing	Die Attach	Wire Bond	Packaging	Plating	
	✓		✓	✓	Leadframe Wire Bond
	✓		✓		Substrate Wire Bond
	✓		✓		Substrate Flip Chip / TCB
	✓		✓		Wafer Level Hybrid, EMIB, TCB, Flip Chip, FOWLP

Source: TechInsights, March 2026



* Excludes TCB
Source: TechInsights, March 2026

Industry Leading Assembly Equipment Portfolio



Die Attach (80% of 2025 Revenue)

Multi-Module Attach



Epoxy / Soft Solder



Flip-chip



Direct Lid Attach



Embedded Bridge Attach



Thermo Compression



Hybrid Bonding



Packaging and Plating (20% of 2025 Revenue)

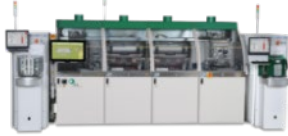
Leadframe Molding



Substrate Molding



Wafer and Panel Molding



Trim and Form



Singulation



Plating



Wet Processing



Serving Blue Chip Customers Across Key End-Markets

Customers

- **Diversified, blue chip customer base**
 - Top 10 customers ~44% of 2025 revenue
 - No customer greater than 10%
- **Supplying leading IDMs, fabless producers and subcontractors**
 - Sell direct to IDMs
 - Sell to fabless producers via subcontractors
 - Orders: 42% IDMs/58% foundries/subcontractors in 2025
- **Long-term relationships**
 - Many exceed 50 years

Foundries/Subcontractors



Independent Device Manufacturers (IDMs)



Fabless IDMs



End-User Markets

Computing
51%



Mobile
17%

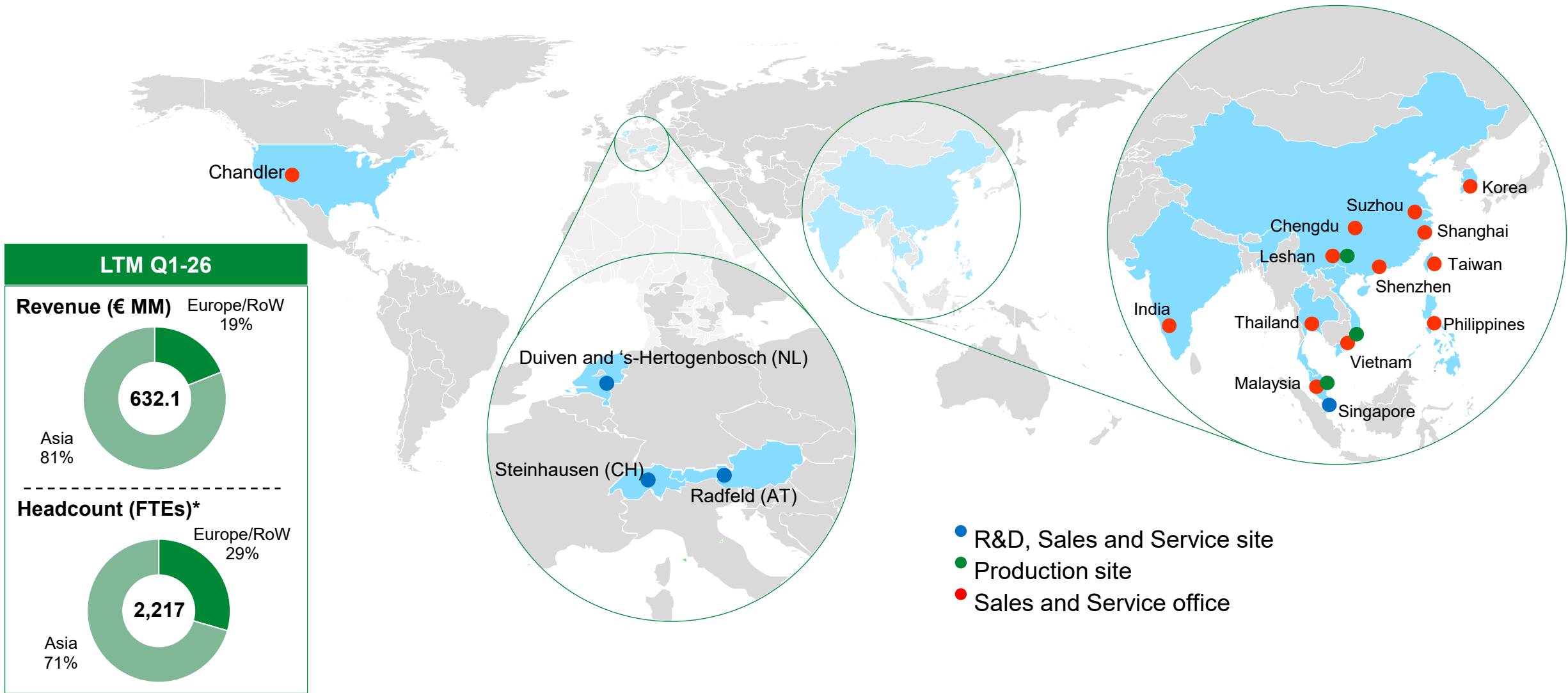


Auto/
Industrial
17%



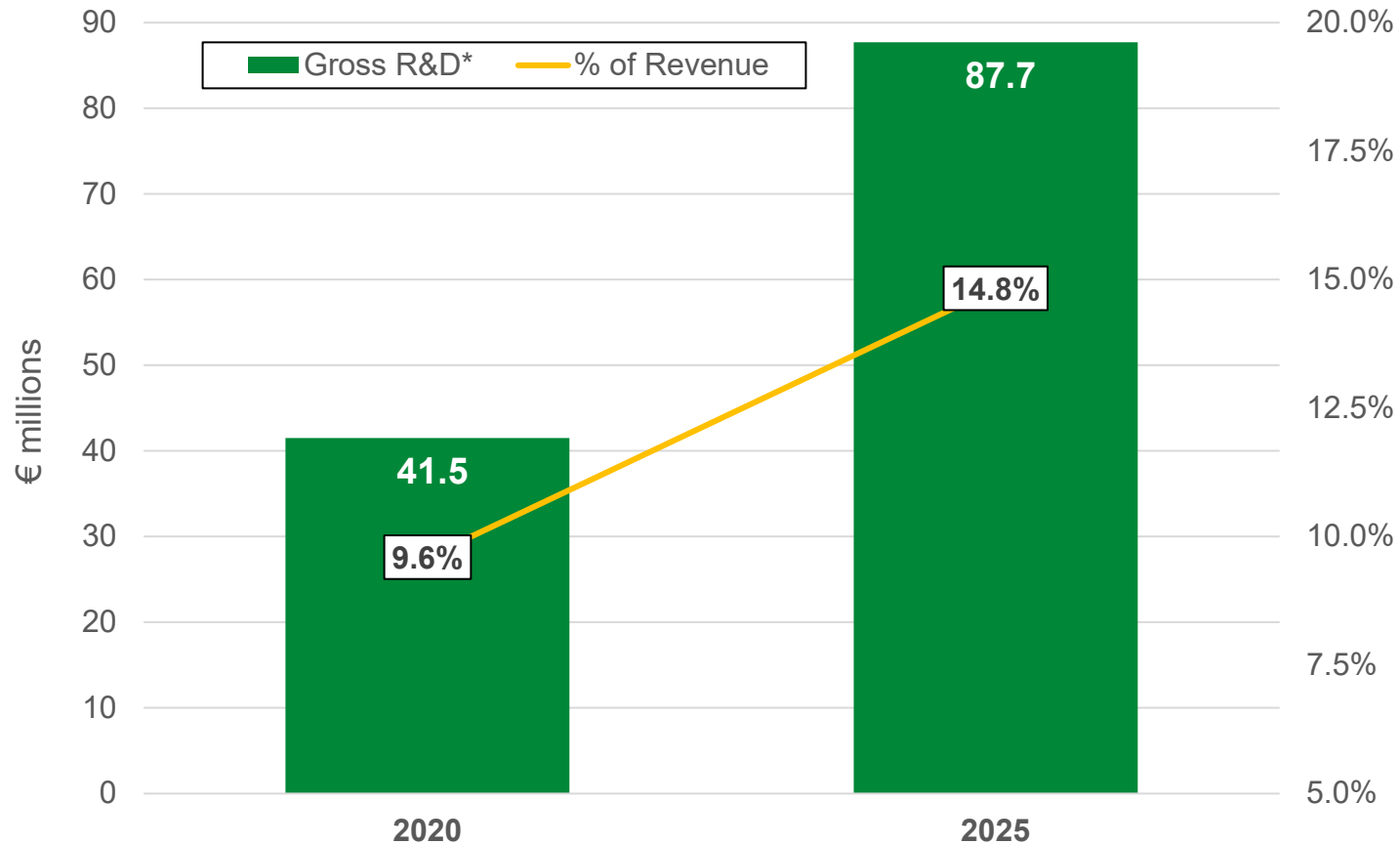
Fiscal 2025 data.

Global Operations Supported by European Development Centers and Asian Production Footprint/Supply Chain



* Headcount per quarter ending. Including temporary headcount.

R&D investment has more than doubled since 2020



* Gross R&D spending excludes impact from capitalization/amortization of R&D costs

Innovation is a key driver of our business:

- New opportunities for each next-generation advanced packaging system

Significant R&D investment in advanced packaging over past 5 years to support:

- New 2.5D/3D IC assembly structures for AI
- Portfolio enhancements for next market upcycle

Key areas of current focus:

- 50 nm accuracy hybrid bonder
- TC Next for memory, logic and photonics applications
- Next generation flip-chip bonder for 2.5D and CoWoS
- 1 μ m accuracy Evo for photonics

Summary Financials

Year Ended December 31, (€ MM)	2023	2024	2025	Q1-25	Q1-26
Orders	548.3	586.7	685.0	131.9	269.7
<i>Growth (%)</i>	-17%	+7%	+17%		+104%
Revenue	578.9	607.5	591.3	144.1	184.9
<i>Growth (%)</i>	-20%	+5%	-3%		+28%
Gross Profit	375.8	395.9	374.3	91.7	117.4
<i>Margin (%)</i>	65%	65%	63%	64%	63%
EBITDA	239.1	224.2	206.8	46.6	73.7
<i>Margin (%)</i>	41%	37%	35%	32%	40%
Operating Income	213.4	195.6	173.1	39.3	63.9
<i>Margin (%)</i>	37%	32%	29%	27%	35%
Net income	177.1	182.0	131.6	31.5	51.6
<i>Margin (%)</i>	31%	30%	22%	22%	28%
Net Cash*	113.0	143.8	36.0	159.4	103.3

* Calculated as Cash, cash equivalents and deposits minus total debt. Excludes lease liabilities.

Long-term growth in cyclical business

- Increased revenue, profitability and market share per cycle

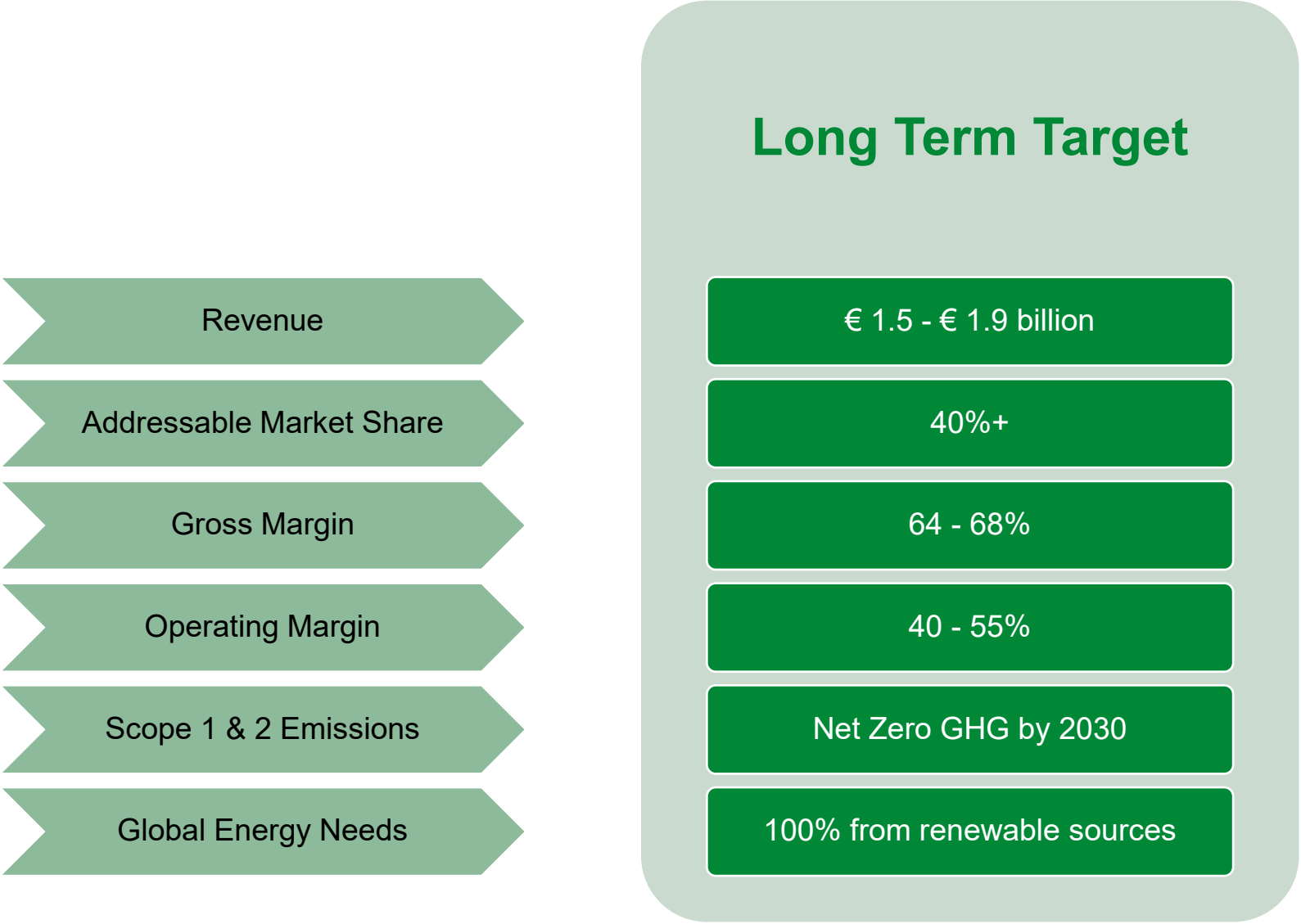
Strong margins and profitability

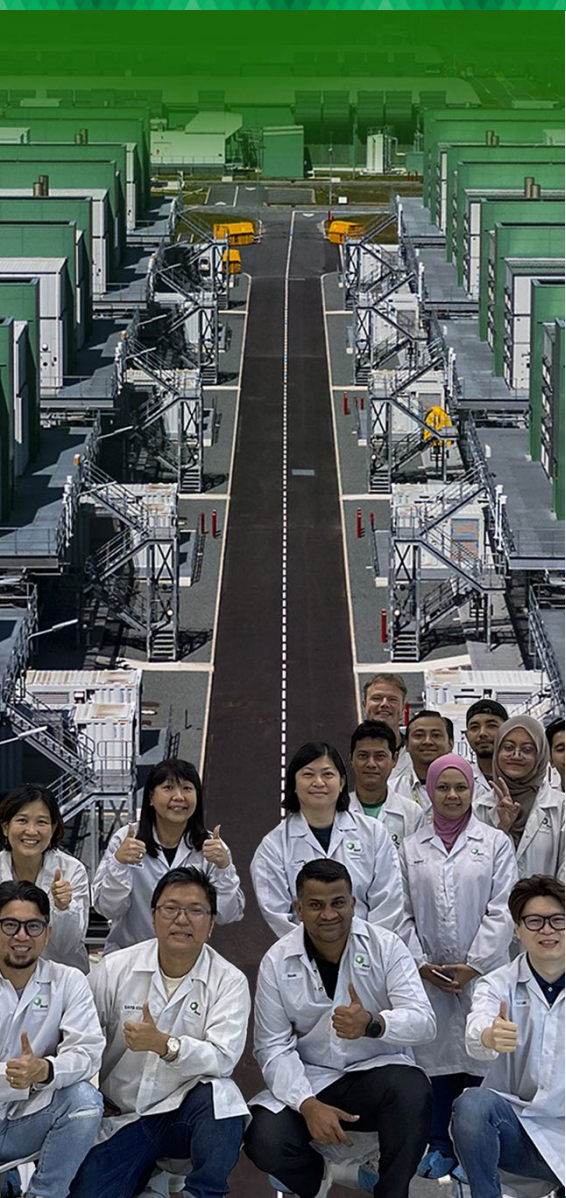
- Increasing through cycle gross and net margins due to advanced packaging product mix, cost control efforts, flexible supply chain and Asian production

Order growth momentum reflects favorable AI influence:

- Orders up 17% vs. 2024 and 104% vs. Q1-25
- Increased demand by Asian subcontractors for 2.5D AI data center and photonics applications
- Increased orders for hybrid bonding systems starting in Q4-25
- Gross margin maintained in 63-65% range past three years
- Renewed revenue growth and operating leverage should drive upward movement in operating and net margins in 2026

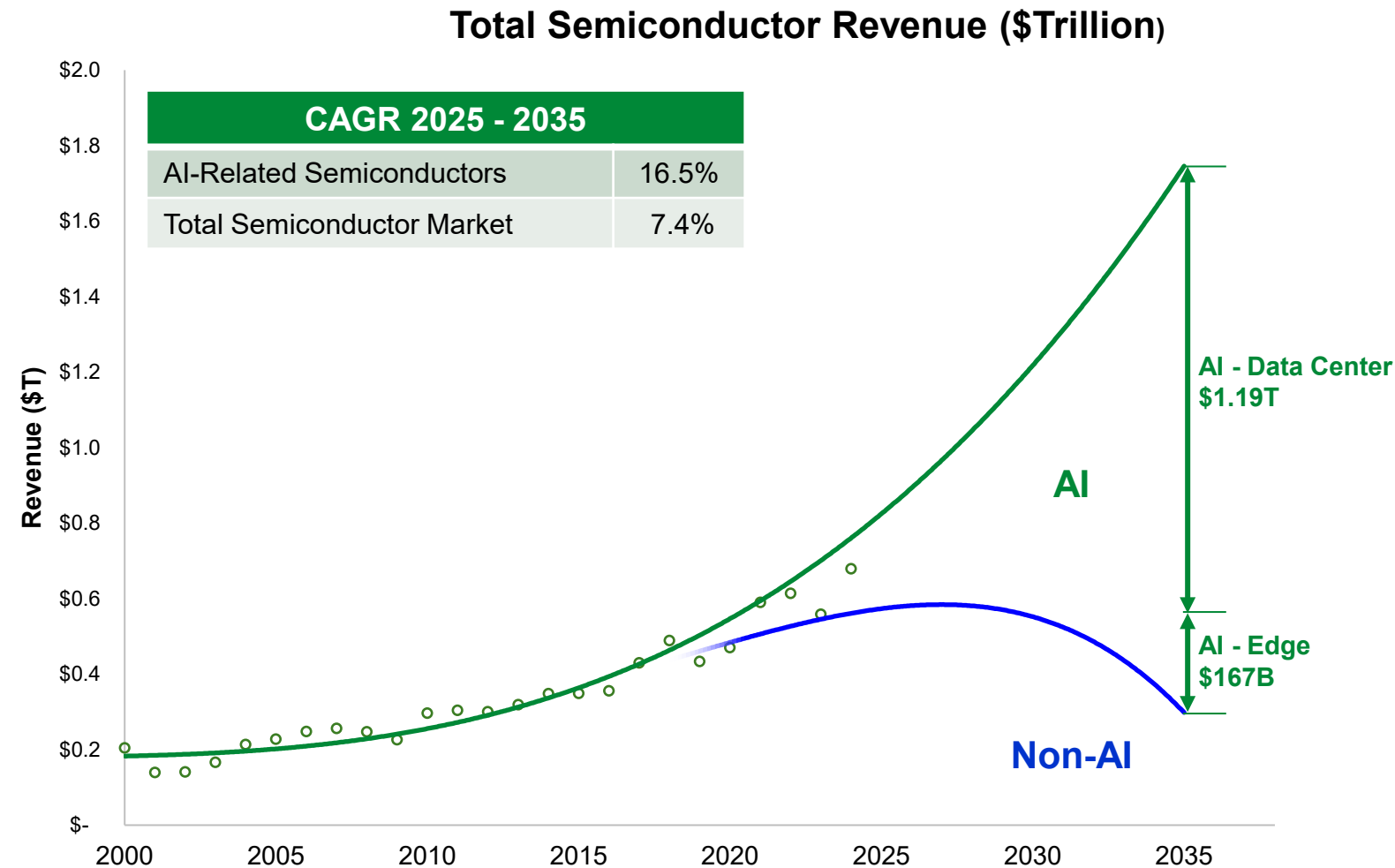
Strong cash generation supports shareholder friendly capital allocation policy





II. MARKET OVERVIEW

AI Driving Long-Term Semiconductor Revenue Growth



Source: TechInsights, December 2025



Humanoid robotics



Autonomous vehicles



AI wearables (AR/VR)



AI smartphones



AI personal computers

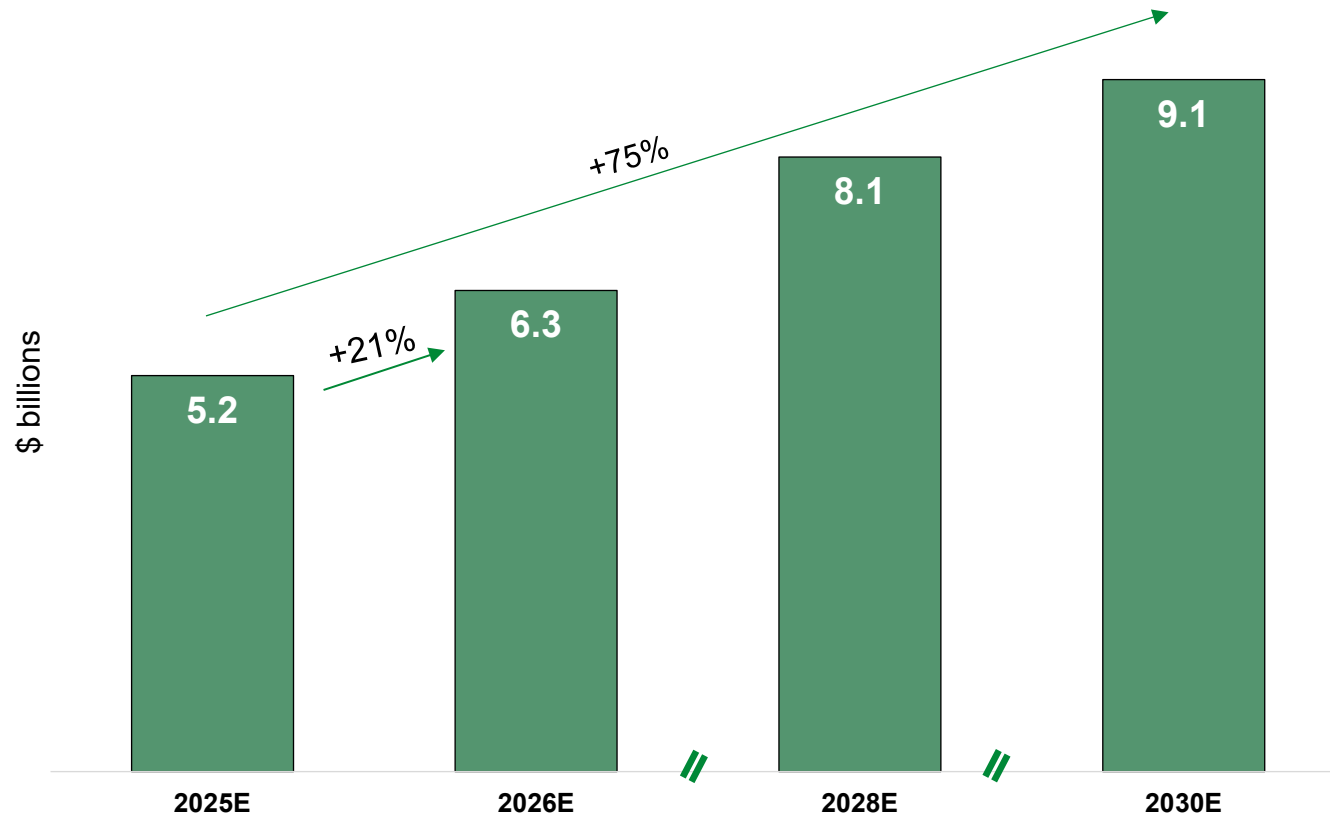


Datacenter AI infrastructure

Approximately \$100B investment in progress or planned

Packaging Fab Projects	# Projects	Cost (\$B)
Taiwan	4	26.1
USA	6	24.5
Europe	4	9.3
Korea	2	9.1
Singapore	1	7.0
China	7	6.3
India	2	6.0
Malaysia	1	1.3
Vietnam	1	1.0

Source: TechInsights, Besi estimates, May 2025



TechInsights forecasts renewed assembly growth

- 21% increase anticipated in 2026
- 75% increase expected 2025-2030
 - Expansion of AI/use cases
 - Recovery of mainstream applications
 - New fabs coming online
- Broad based advanced packaging growth expected

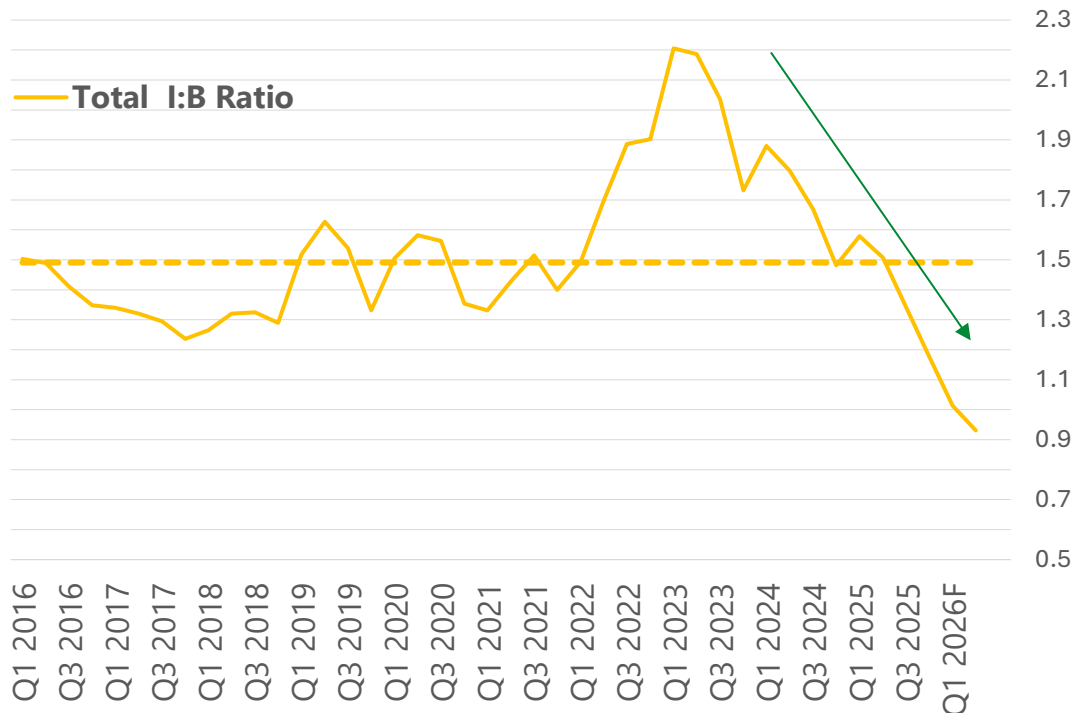
Besi expects to significantly outperform projected assembly market growth

Source: TechInsights, March 2026. Assembly equipment revenue excludes service revenue

Signs of Improving Market Conditions

Semi Inventory/Bookings Ratio Indicates Order Growth Significantly Outpacing Inventory Levels

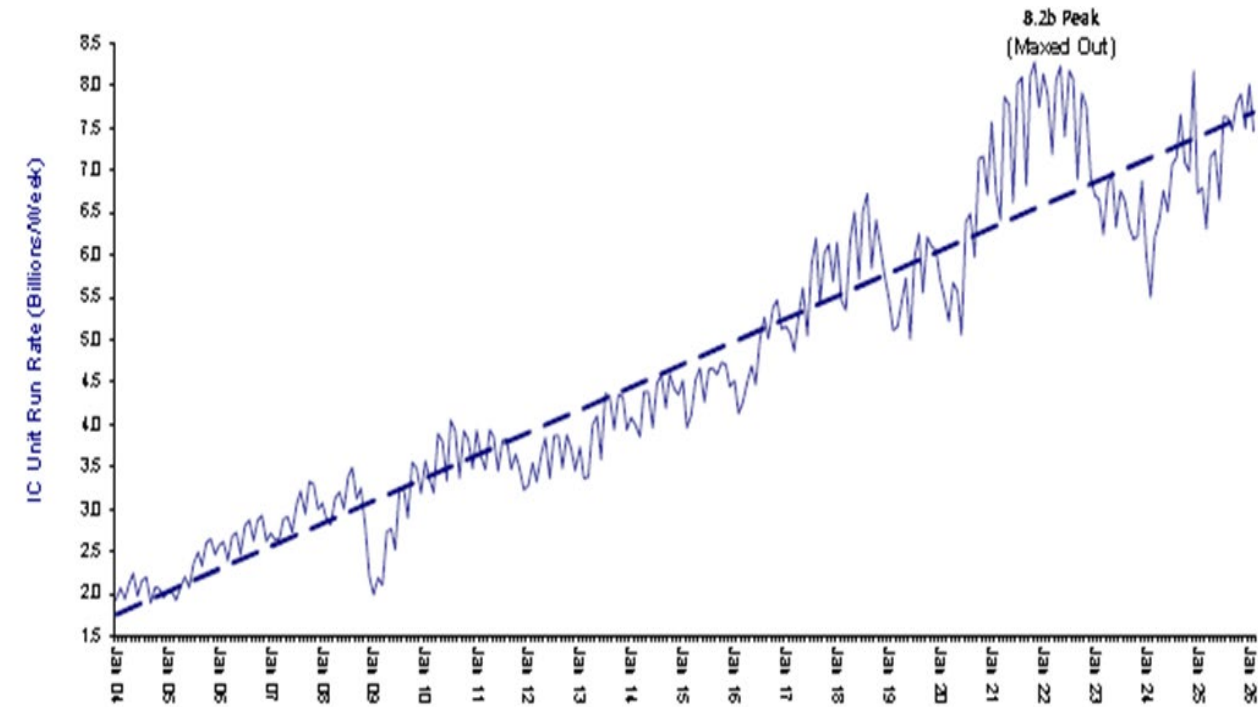
IC Inventories
(Q1 2016 – Q2 2026F)



Source: TechInsights, April 2026

Favorable IC Unit Growth Trends Back to Long Term Trend Line

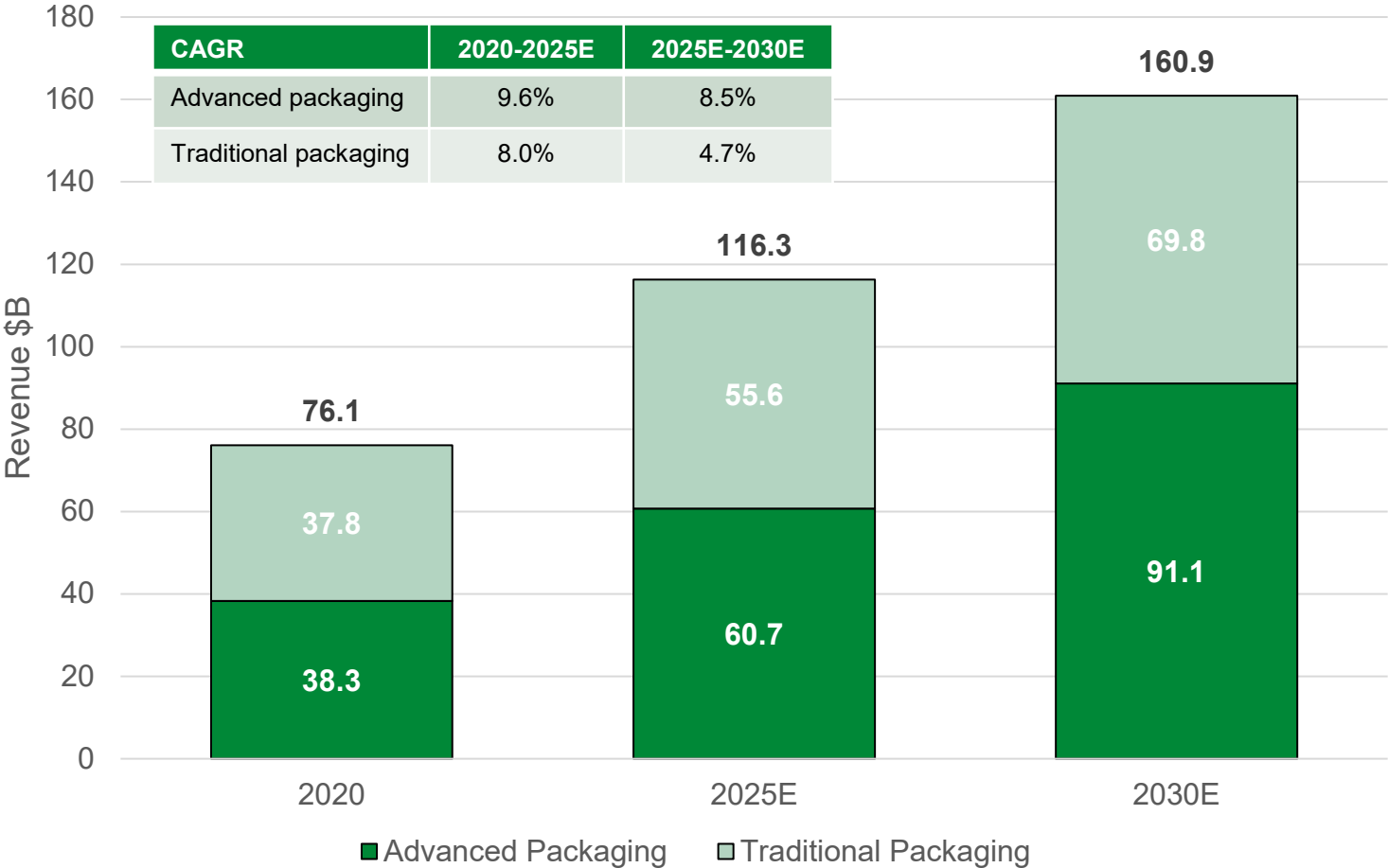
Total Weekly IC Unit Shipments
(2004-2026)



Source: Future Horizons, April 2026

Advanced Packaging Revenue Forecast to Grow Rapidly

2.5D/3D Fastest Growing Segment

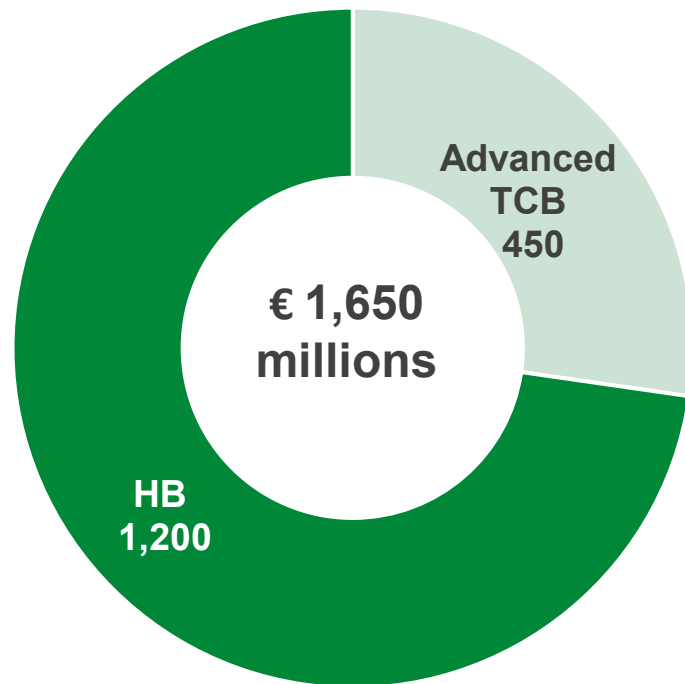


Besi portfolio well positioned by node size and accuracy

- ~70% of Besi equipment revenue from advanced packaging
- ~60% equipment revenue from advanced die placement (< 7 micron accuracy)
- ~50% of revenue AI-related

Source: Yole, August 2025

Estimated 2030 Hybrid Bonding and Advanced TCB Market Size (€ millions)



Hybrid bonding estimated to be largest assembly segment by 2030

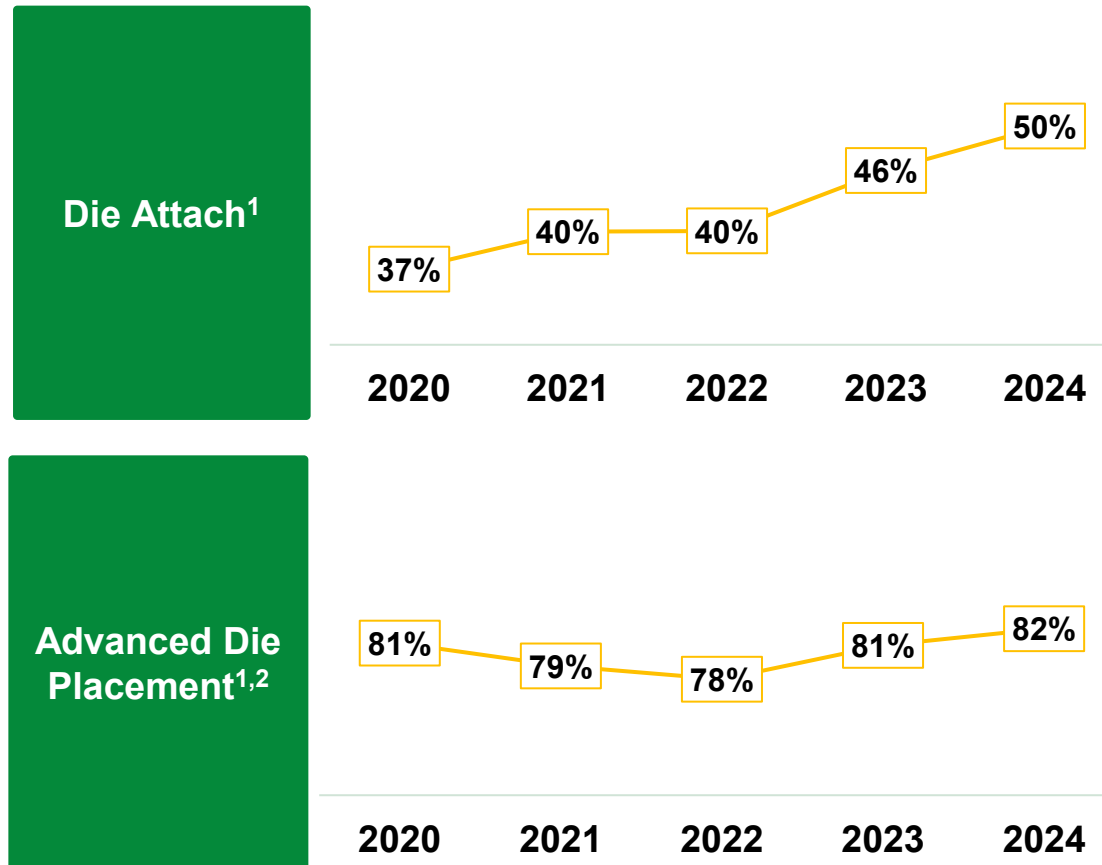
- Assumes transition from TCB to hybrid bonding in HBM5
- Estimated market size in 2030 = ~350 units (mid case). ~1,500 units cumulatively

Besi entered Fluxless TCB market

- Emerging market with significant growth potential
- Focused on highest value added advanced chiplet, memory, logic and photonics applications
- Estimated market size in 2030 = ~100 units (mid case). ~500 units cumulatively

Source: Besi estimates. Mid case scenario hybrid bonding

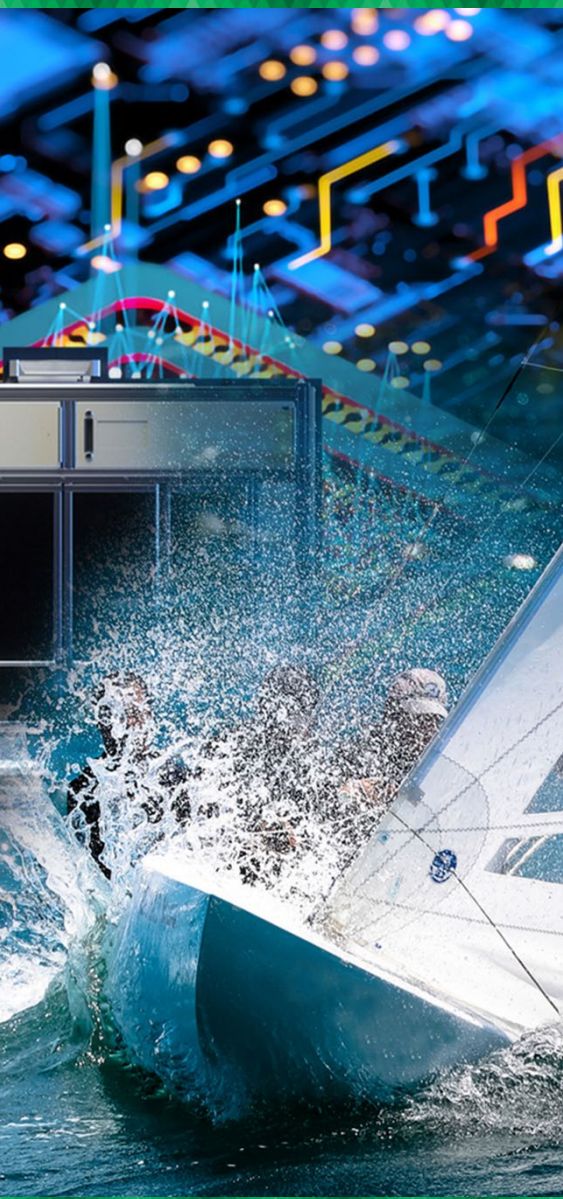
Leading Market Shares in Besi's Key Die Attach Markets



Source: TechInsights, May 2025

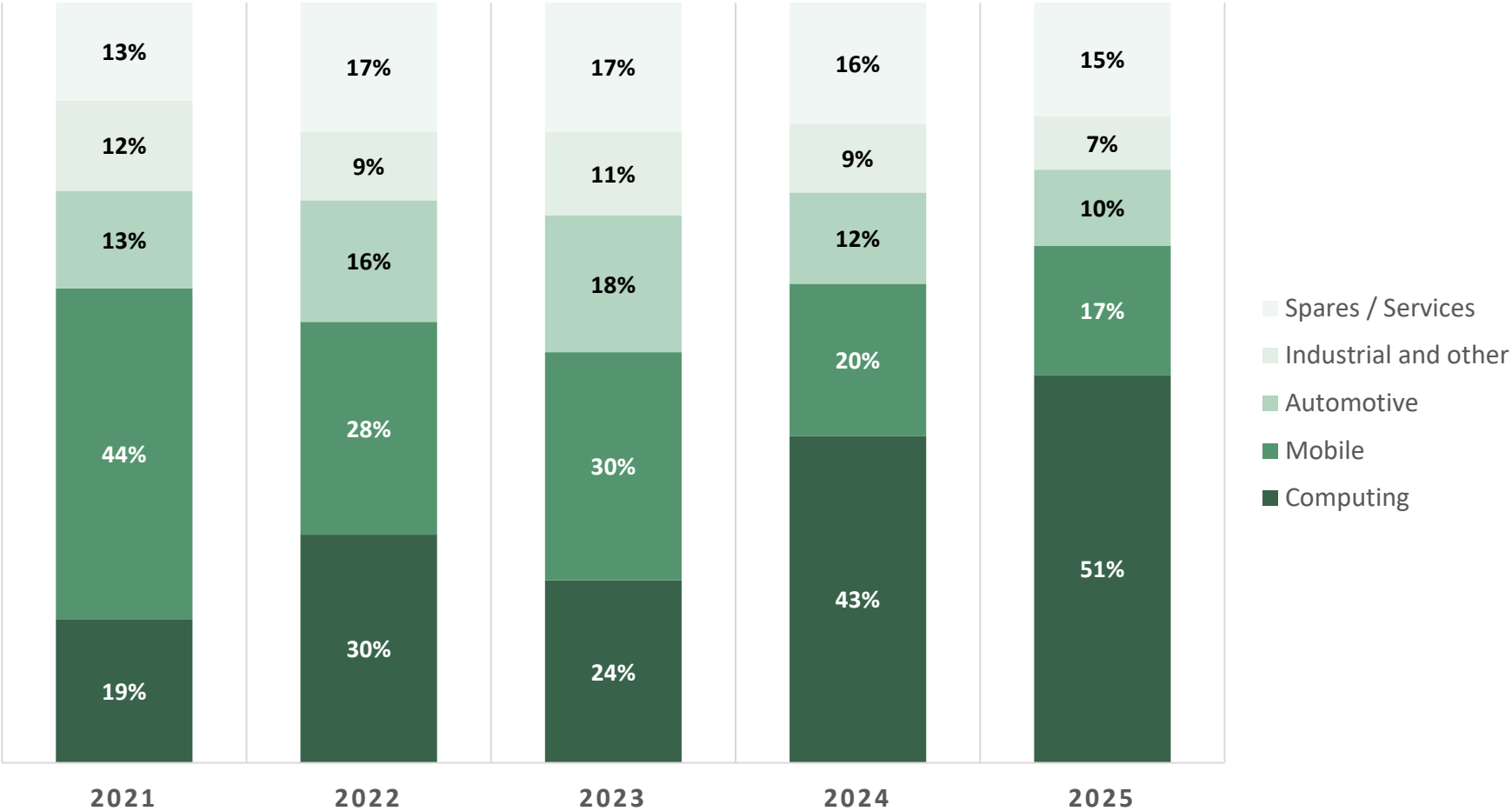
¹) Excludes TCB, wire bonding, dicing, and other

²) Advanced die placement defined as <7 micron accuracy per TechInsights



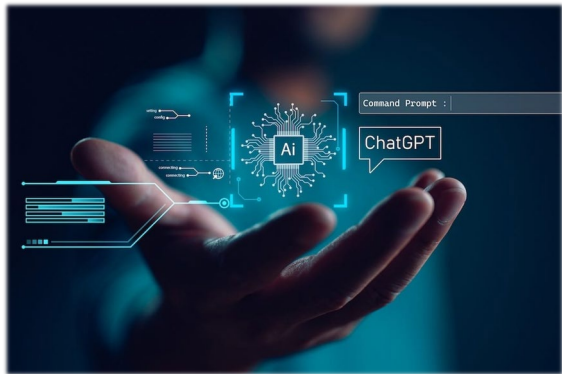
III. END-USER MARKET TRENDS

AI Driving Change in Besi's End-User Application Revenue



End market as % of total revenue

Principal Growth Drivers in Besi's End-User Markets

Computing	Mobile	Automotive	Industrial / Other
			
Agentic AI	On Device AI	Autonomous Driving	Factory Automation
• Datacenters • Si Photonics • Edge AI tablets/PC/laptops • Gaming	• Adv. cameras & 3D imaging • 5G advanced → 6G • Under display biometric ID • New AR/VR devices	• Advanced cameras/sensors • Vehicle electrification • SiC & GaN power devices • Connectivity/infotainment	• Robotics • Smart grid • Industrial IoT • Clean energy

Advanced Packaging Solutions Critical to Development of Next Generation Applications

Besi's Advanced Packaging Solutions

- Hybrid bonding
- TCB chip-to-wafer
- High accuracy flip-chip
- Fan-out, embedded bridge
- EVO multi module
- Thermal management
- Wafer/substrate molding

2.5D/3D Process Applications

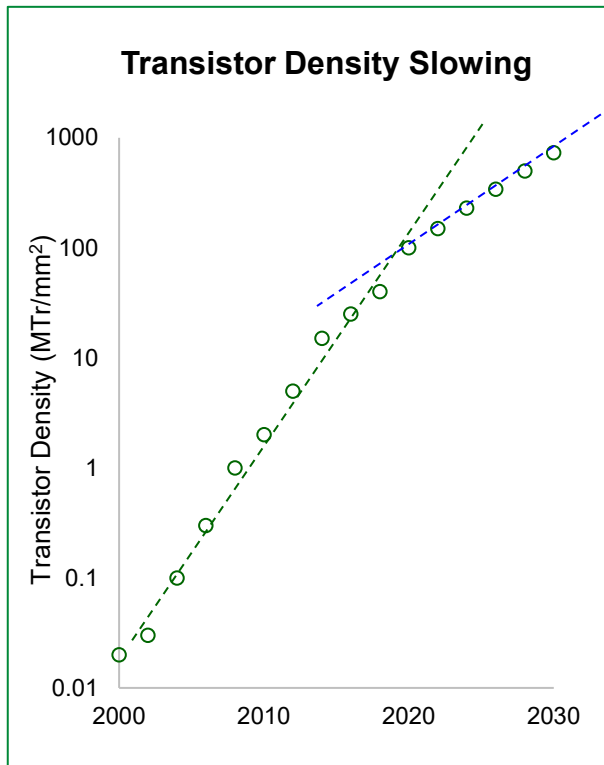
- 3D IC logic
- High Bandwidth Memory (HBM)
- Chip on Wafer on Substrate (CoWos)
- Photonics chiplets
- Die embedding
- Thermal lid attach
- Encapsulation

End-User Applications

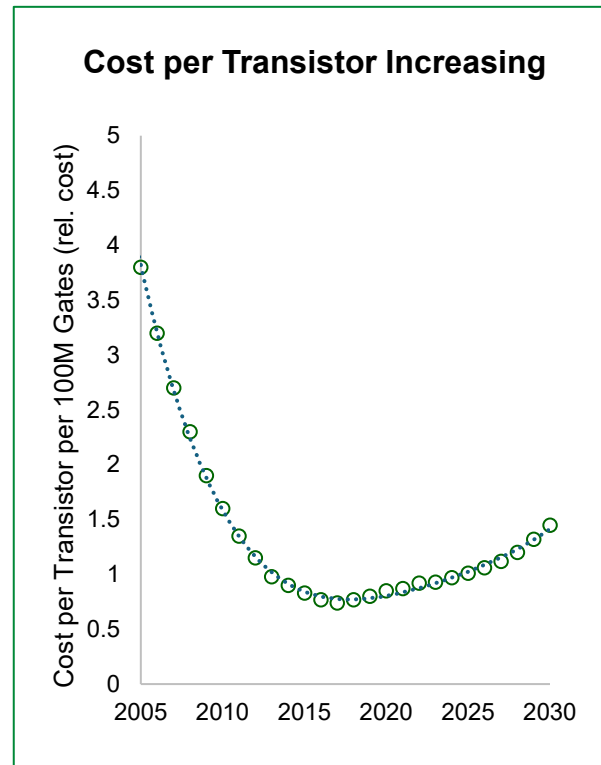
- Mobile:
 - On-device AI
 - Advanced cameras and sensors
 - 5G/6G mobile
- Computing:
 - Datacenters
 - Edge AI laptops/PCs
 - New AR/VR devices
- Auto/Industrial:
 - Autonomous driving
 - Vehicle electrification
 - Smart grid/clean energy

Slowing of Moore's Law Accelerates Adoption of Chiplets and 3DIC

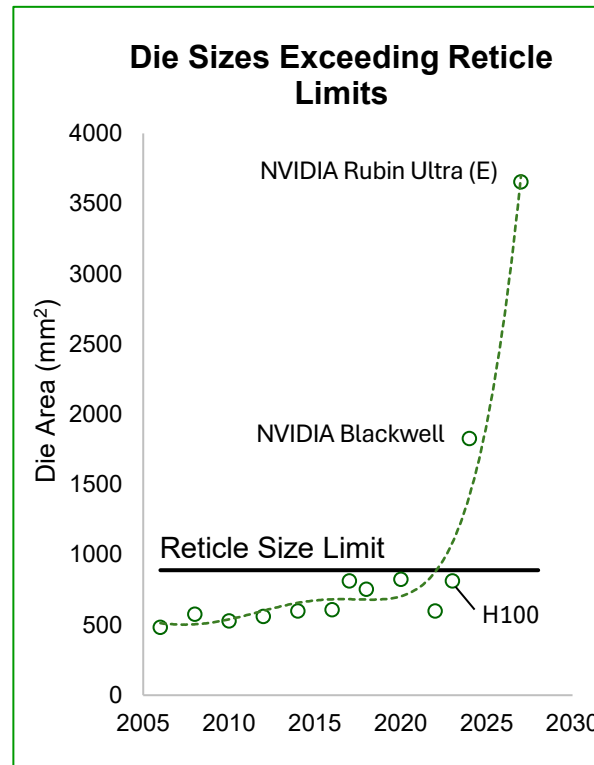
- **Moore's Law slowing** as data volumes grow exponentially and commercial applications expand
- **Customers adopting chiplets**, connected via hybrid bonding and TCB, to optimize device function per node and reduce cost



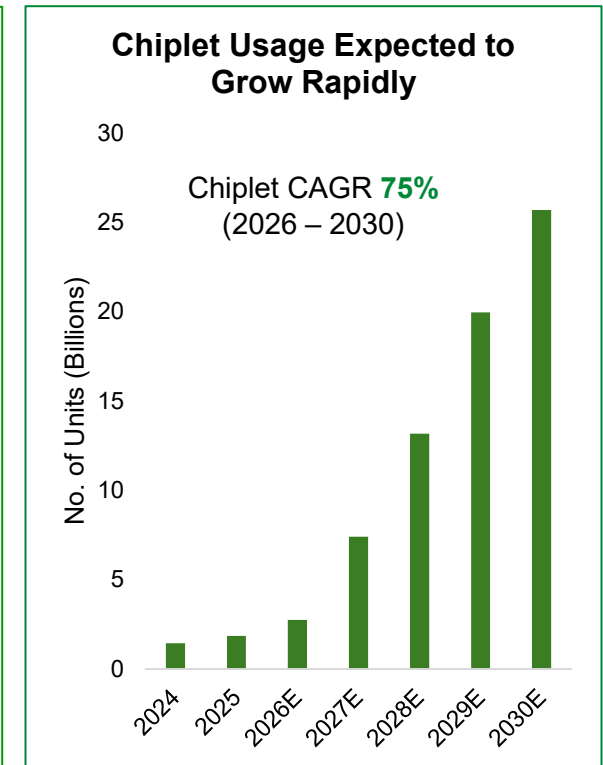
Source: IRDS 2023 Edition



Source: Tom's Hardware, IEDM 2023 - Google



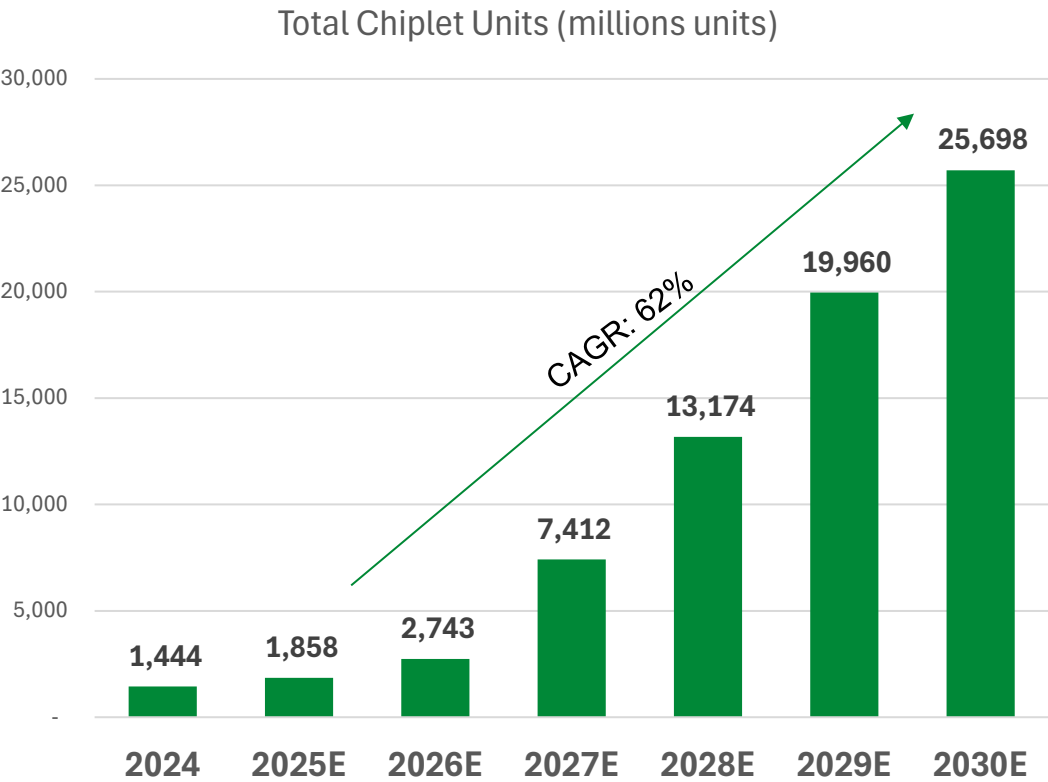
Source: Besi



Source: TechInsights, December 2025

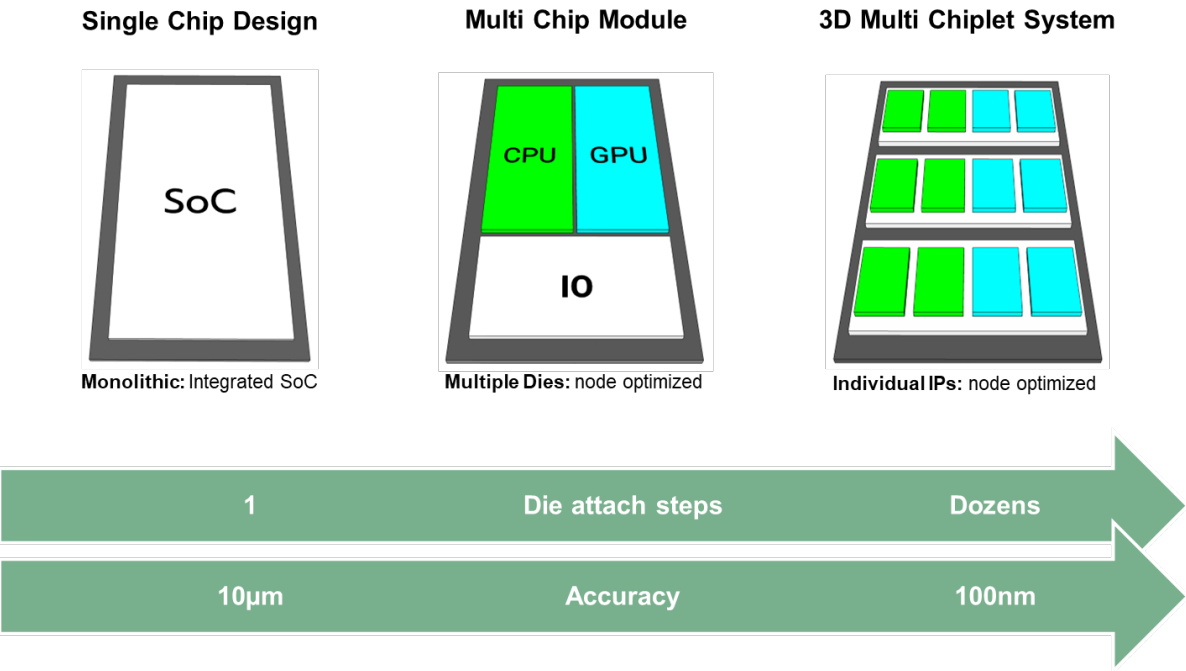
Chiplet Usage Increasing Rapidly Due to Favorable Economics for Advanced Applications

Chiplet Usage Expected to Grow Rapidly



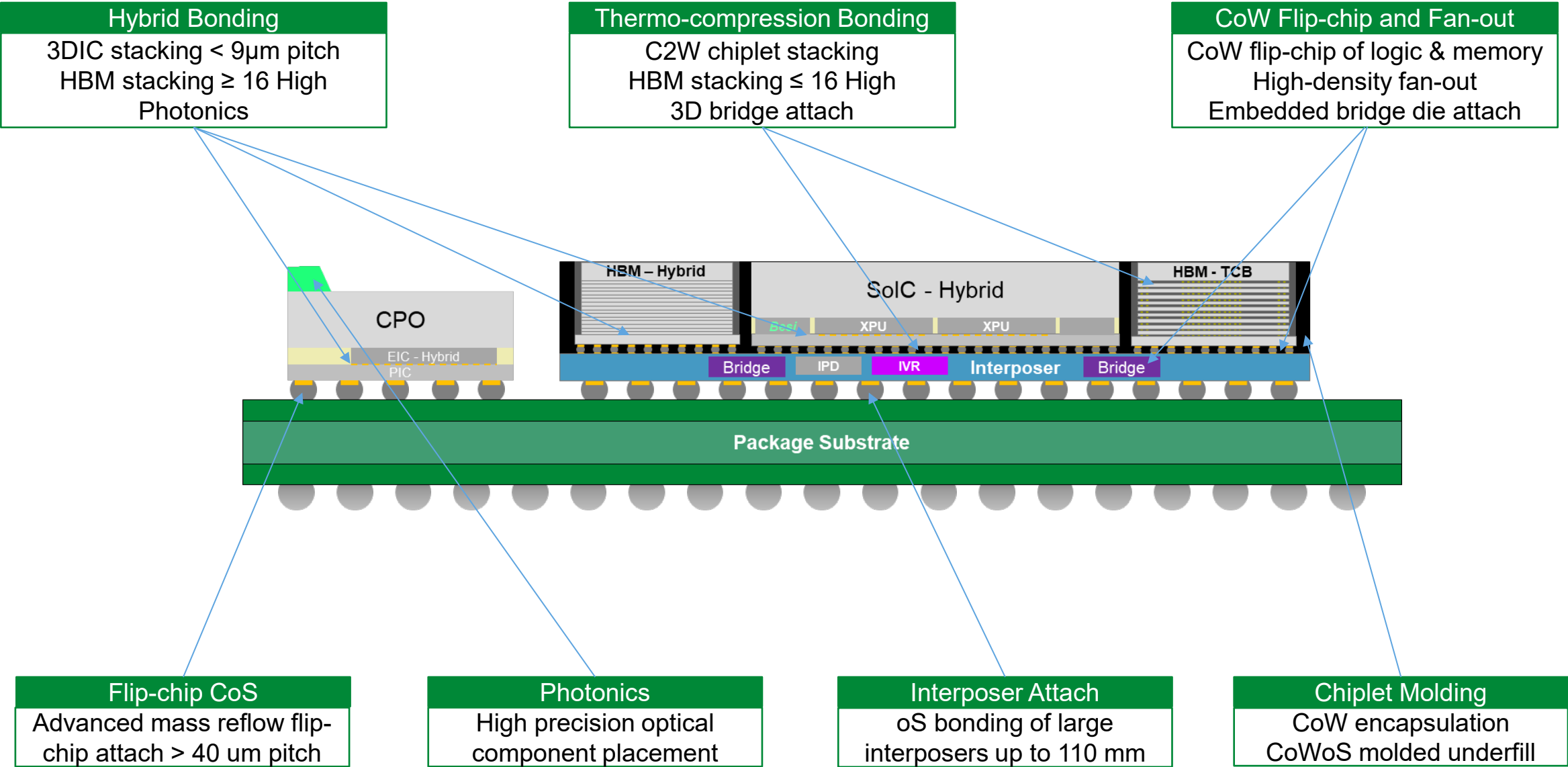
Source: TechInsights, December 2025

Chiplet Adoption Drives Higher Capital Intensity

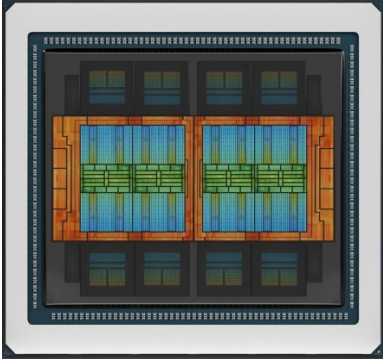
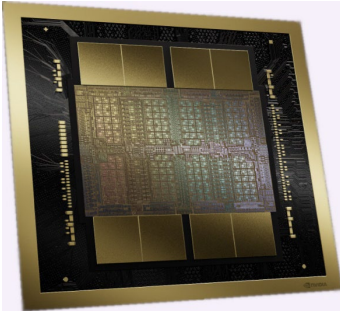
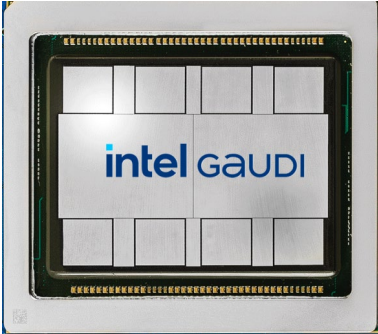
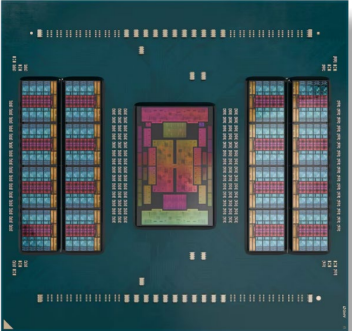
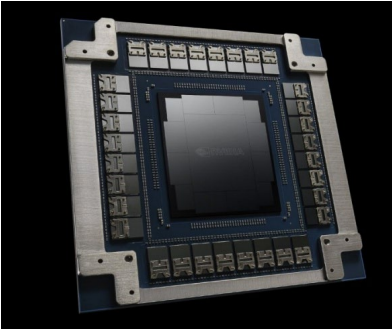
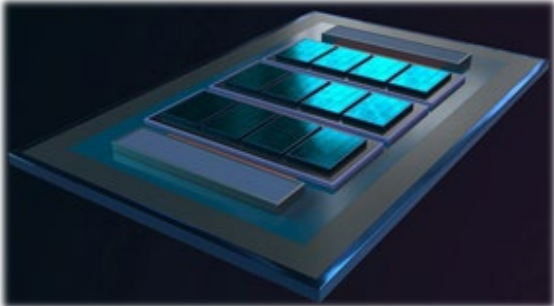


Source: Intel

AI Chiplet Packages Require a Variety of Advanced Packaging Solutions

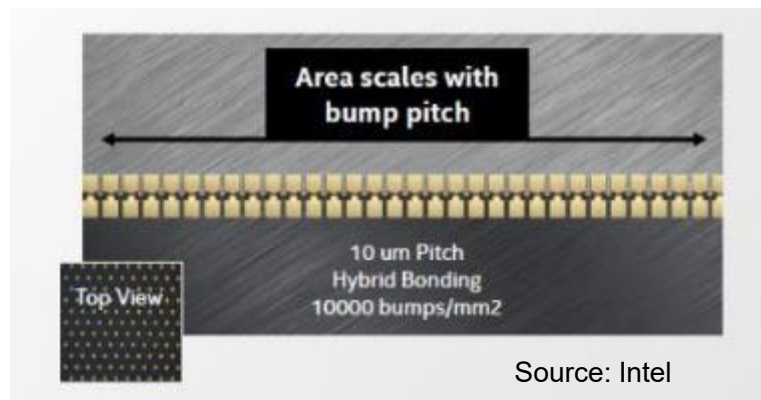


Advanced Datacenter Chips Adopting Chiplet Architectures

AMD	NVIDIA	Intel
MI350 Accelerator  CoWoS-S (Hybrid Bonding)	B200 (Blackwell) GPU  CoWoS-L package	Gaudi 3 AI Accelerator  CoWoS-S package
Zen 5 EPYC CPU  SolC (Hybrid Bonding)	Spectrum X Network Switch  CoWoS-S with CPO (Hybrid Bonding)	Clearwater Forest CPU  Foveros Direct (Hybrid Bonding)

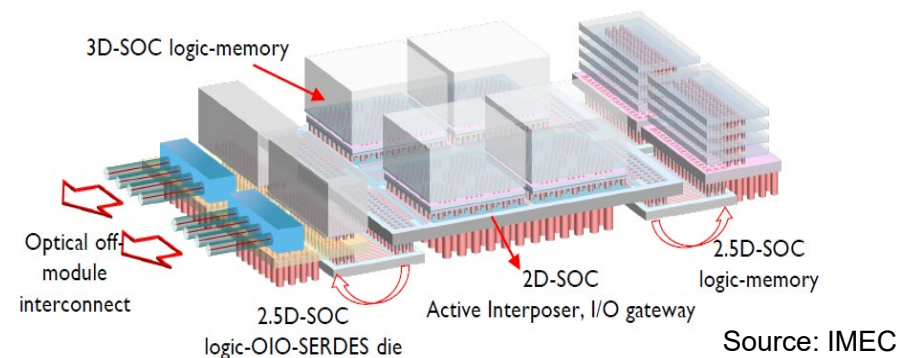
Hybrid Bonding Enables Faster, More Complex Devices With Submicron Placement Accuracy and Less Power/Heat Generation

Direct Cu-Cu 3D Interconnect



1,000x increase in contact density

Heterogeneous Chiplet Integration



More transistors per package

New Chip Architectures

- Quasi-monolithic 3D
- Optimal use of nodes
- Customized designs
- Highly configurable

Increased Performance

- Highest compute power
- Increased data transfer
- Higher bandwidth
- Higher speed

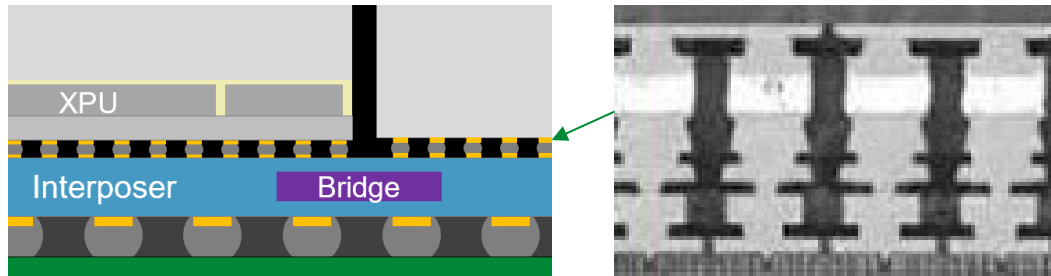
Lower Cost of Ownership

- Higher die yield
- Lower energy per bit
- Lower cost per contact
- Lower heat dissipation

Hybrid Bonding is Technology of Choice for 3D Chiplet Stacking

TCB Micro-bump C2W

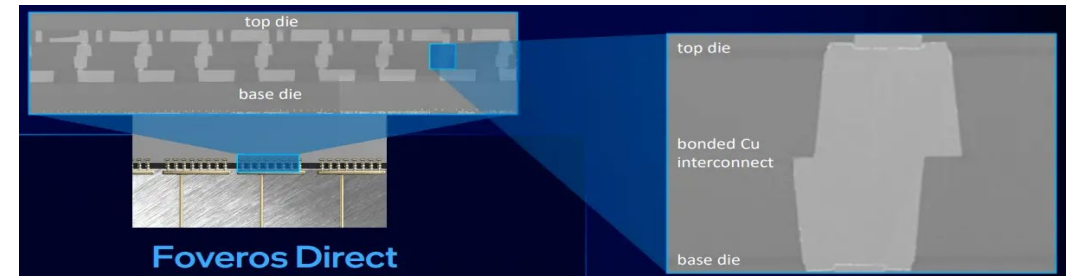
TCB C2W used for lower density, less performance critical applications, such as CoW interposer assembly



Source: INTEL

Hybrid Bonding

Highest performance interconnect to create 3D ICs in front-end wafer fabrication process

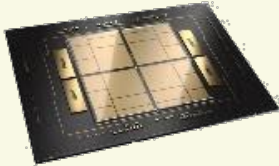
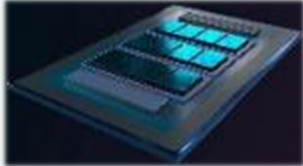
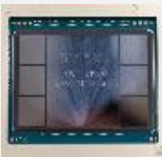
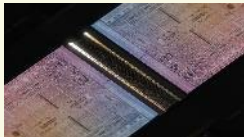


Source: INTEL

Micro-bump C2W TCB	Performance Factor*	Hybrid Bonding
1X	Interconnect Density	15X
1X	Speed	11.9X
1X	Bandwidth Density	191X
1X	Energy Efficient Performance, EEP**	>100X
10X	Cost per Interconnect***	1X

Data source: * TSMC 2023, ** TSMC 2025, ***Besi estimate based on max interconnect density

Important Process Step In Future Product Roadmaps

	SoC	Split Die	Chiplets and Hybrid Bonding	
AMD	Opteron Server CPUs	1st Gen EPYC CPU (2017)	2nd Gen EPYC (2019)	3rd Gen EPYC (2022) with Hybrid Bonding
				
intel		Sapphire Rapids CPU (2023)	Clearwater Forest CPU w/ Hybrid Bonding (2025)	
				
nvidia	H100 GPU	B100 GPU (2024)	Future chiplet architectures	
				
Apple	M1 MaxCPU	M1 Ultra CPU (2022)		
				

Increased Hybrid Bonding Use Cases and Products in the News

	"TSMC says COUPE platform set for production as Samsung outlines Silicon Photonics push" <i>Digitimes Asia. April 2026</i> "Taiwan's TSMC advanced packaging fabs on schedule" TSMC is expanding its advanced packaging capacity, especially SoIC hybrid bonding, which enables 3D stacking. <i>Taiwan News. March 2026</i>	SAMSUNG "Samsung, SK Hynix reportedly ramp hybrid bonding push for next-gen HBM" <i>Digitimes Asia. April 2026</i> "Samsung unveils HBM4E, showcasing comprehensive AI solutions, NVIDIA partnership and Vision at NVIDIA GTC 2026" <i>Samsung. March 2026</i> "Samsung Electronics launches silicon photonics foundry business." Building production ready photonic integrated circuits now with aim to scale toward co-packaged optics by 2030" <i>Design & Reuse. April 2026</i>
	"Semiconductor Equipment's Next Gold Mine" Broadcom XDSiP 3.5D platform's core feature is hybrid copper bonding <i>36Kr Europe. March 2026</i> "Broadcom paves path for the 200T AI Era" Broadcom highlights optical roadmap, including co-packaged optics and photonics enabled scaling for future AI networks. <i>Broadcom. March 2026</i>	 "How Micron is Looking to Win the HBM Wars" Micron frames hybrid bonding as part of its 2026 HBM4 transition. <i>Forbes. April 2026</i>
	"Hybrid bonding expands from logic to memory: SK Hynix, Applied Materials, Besi drive co-optimization to scale next-gen HBM" <i>Counterpoint. April 2026</i> "SK Hynix eyes hybrid bonding for HBM5 launch by 2029" <i>Counterpoint. April 2026</i>	 "Apple M5 Pro and M5 Max to feature 3D hybrid bonding". <i>Netfox. March 2026</i>
	"NVIDIA Rubin Ultra and Feynman reportedly to boost TSMC SoIC; Besi, Applied Materials, TEL to benefit" <i>Trendforce. March 2026</i> "NVIDIA Feynman GPU gets 3D die-stacking, custom HBM & Next gen Rosa CPU" <i>Wccfttech. March 2026</i>	 "Coherent demonstrates multiple co-packaged optics technologies at OFC 2026." Coherent to show how photonics stack can meet bandwidth and efficiency needs of AI datacenters. <i>Coherent. March 2026</i>  "Engineering the Future of AI" AMD has ongoing innovation in 2.5D, 3D and hybrid bonding as part of heterogeneous packaging for future Instinct accelerators <i>AMD Blog. November 2025</i>

1 Today's Industry Standard

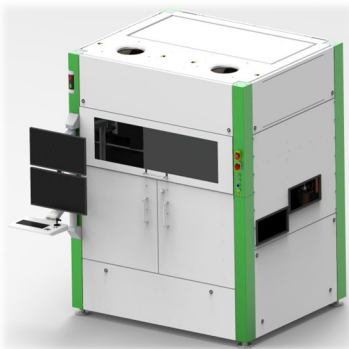
8800 CHAMEO ultra plus AC



Alignment Accuracy: 100 nm
Pad Pitch: <6µm
Die Stacking UPH: 2,000
Installed Base: >150

2 Launch in 2026

3300 HYBRID N50



Alignment Accuracy: 50 nm
Pad Pitch: <3µm
Die Stacking UPH: >3,000

3 Roadmap to 25 nm and beyond

HYBRID Next Generation

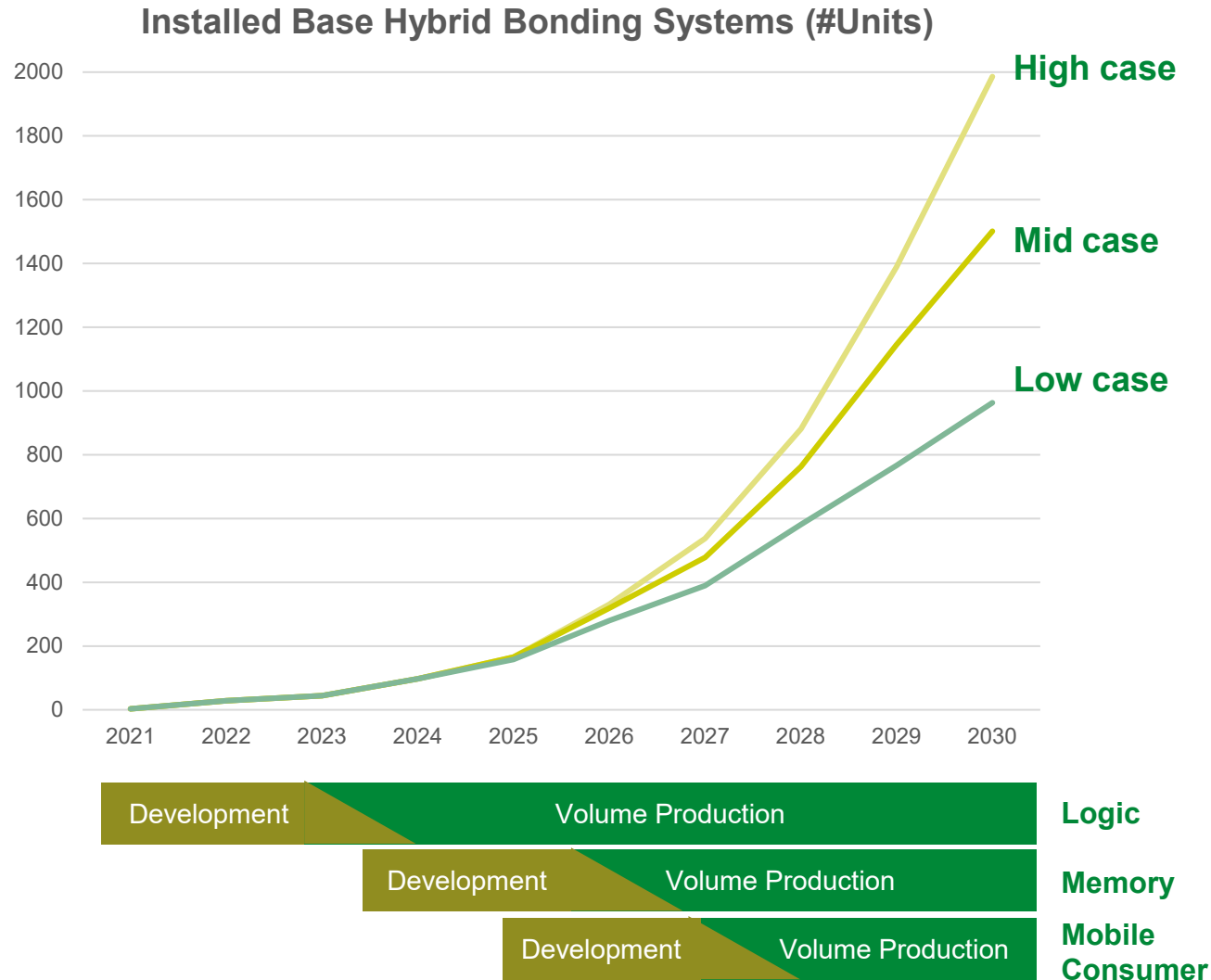


Alignment Accuracy: 25 nm
Pad Pitch: <1µm
Die Stacking UPH: >5,000

Logic roadmap – driven by accuracy

Memory roadmap – driven by throughput

Hybrid Bonding Market Potential – Logic and Memory Cases Confirmed



Estimated 960 – 2,000 systems cumulatively by 2030
Up ~7% for low and mid cases vs. 2024 CMD

Low case (logic):

- Logic adoption confirmed
 - AMD and Intel progressing as expected
 - Broadcom adopting SoIC for custom AI ASICs
 - High-end PC/laptop CPUs expected to adopt SoIC by end of 2025
 - Many AI device players in development

Mid case (Memory & CPO):

- Memory adoption confirmed
 - All leading players evaluating both HB and TCB for HBM4
 - First hybrid bonded HBM4e 16 high stacks in 2026
 - HBM 5: Hybrid bonding only
- Co-packed optics moves from upside potential to reality

High case:

- Emerging applications becoming more tangible
 - Smart glasses adopting D2W fusion bonding
 - Micro displays
 - Sensors
 - Smartphones

Source: Besi estimates, June 2025

TC Next Complements Hybrid Bonding To Offer Customers Complete Portfolio for Next Gen AI Applications

9800 TC Next Thermo Compression Bonder

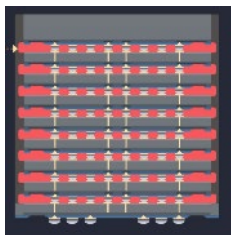


Key Features

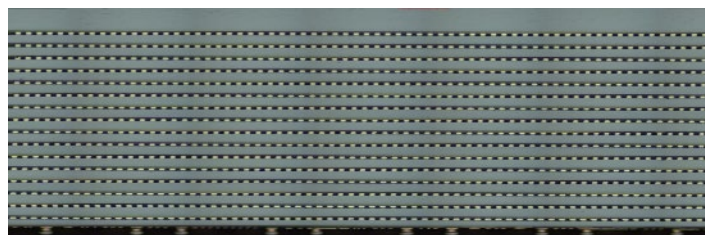
Best in Class C2W TCB for Chiplet Packages

- NCF, NCP, TC-CUF and TC fluxless bonding processes with micro-inert chamber
- Chip-to-wafer and chip-to-substrate configurations
- 0.5 um placement accuracy for ultra fine pitch chiplets
- High throughput up to 2500 CPH
- Front-end automation and process control
- AI^x active bond quality monitoring

HBM Stacking up to 16 die high

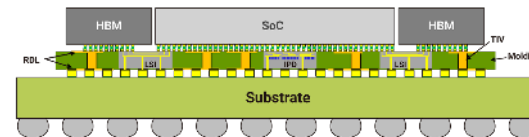


Source: SK Hynix

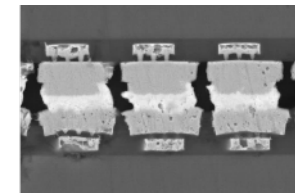


16 HBM die stacking example

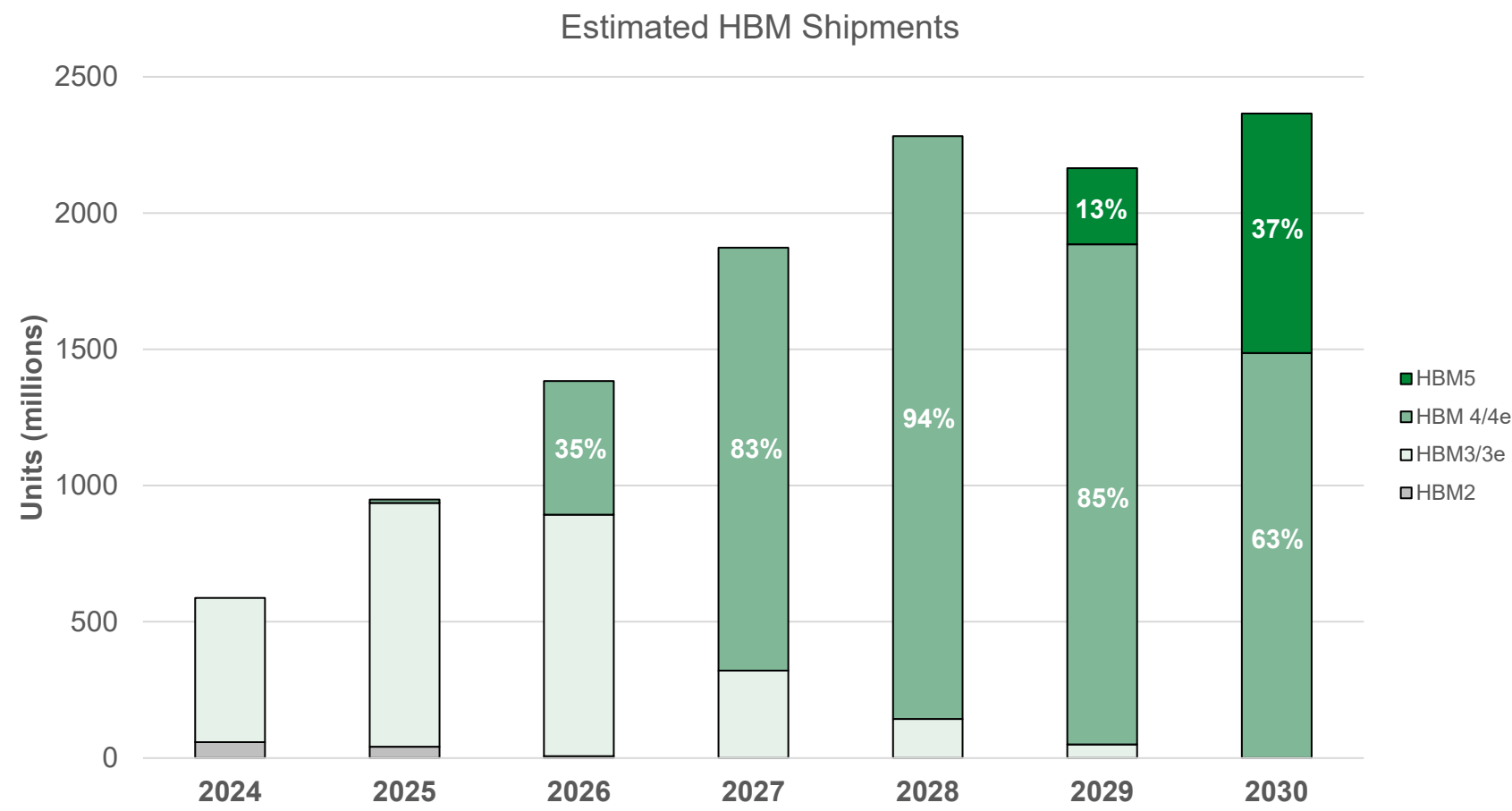
AI XPU and Advanced Logic Applications



Source: TSMC



HBM4/5 Adoption Expected to Accelerate in 2026. Important Drivers for Both Hybrid Bonding and TCB Next Growth



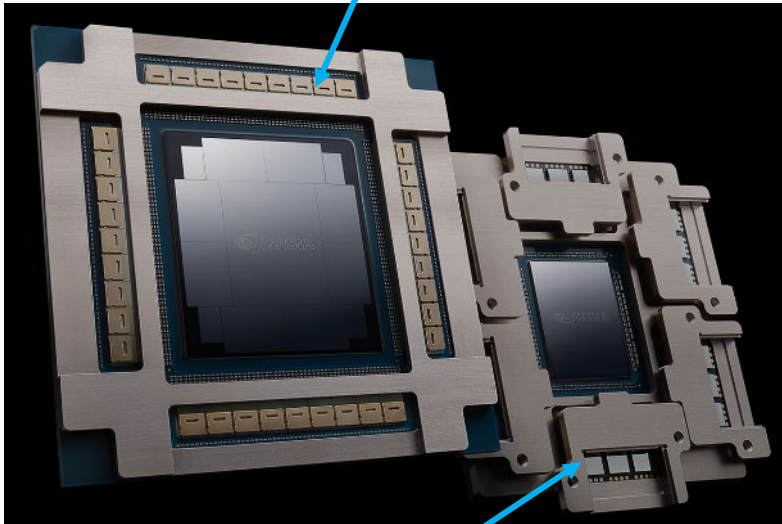
Source: TechInsights, December 2025

Silicon Photonics Another Driver of 2.5D/3D Assembly Growth

NVIDIA confirms Hybrid Bonding adoption in CPO switches

Introduced family of network switch products using co-packaged optics (CPO) in May 2025

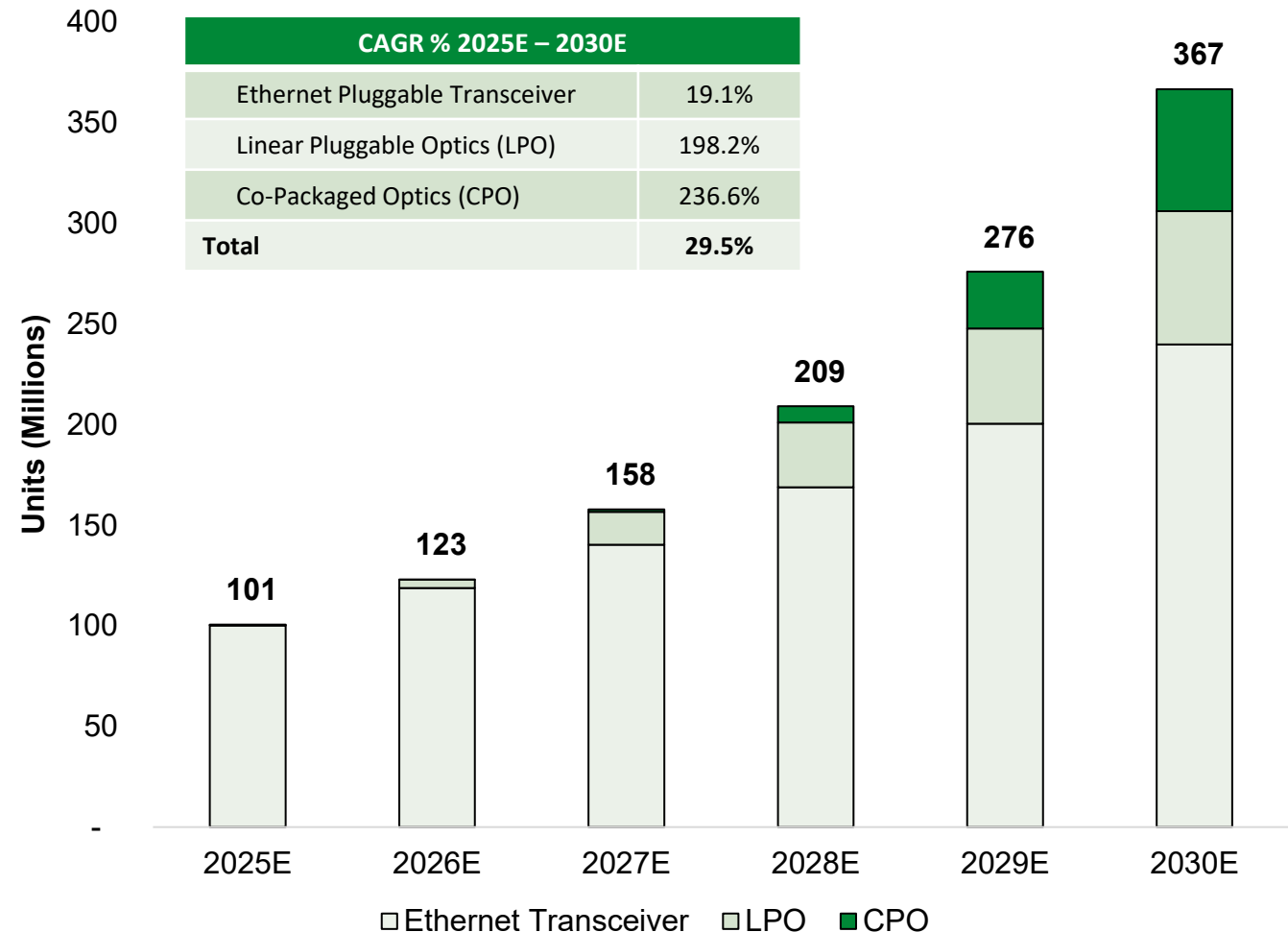
Spectrum-X™ Ethernet switch with 36 3D photonics chiplets



Quantum-X800 InfiniBand switch with 18 3D Photonics chiplets

- TSMC's COUPE technology uses hybrid bonding to assemble the 3D photonic chiplets
- Multiple hybrid bonded chiplets per switch device

Transceiver, LPO and CPO Unit Volume Forecast



Source: LightCounting, October 2025

Generative AI accelerating

- Drives investments in next generation devices and applications requiring advanced packaging

New use cases emerging from cloud to edge computing to co-packaged optics

Promise of AI **requires new 2.5D/3D assembly solutions** to further Moore's Law

Advanced packaging one of **key differentiators to realize AI promise** including energy efficient data center performance and new consumer edge AI devices

Accelerated advanced packaging innovation expected in 2026-2030 across logic, memory, consumer and I/O

Expanded R&D investment continues

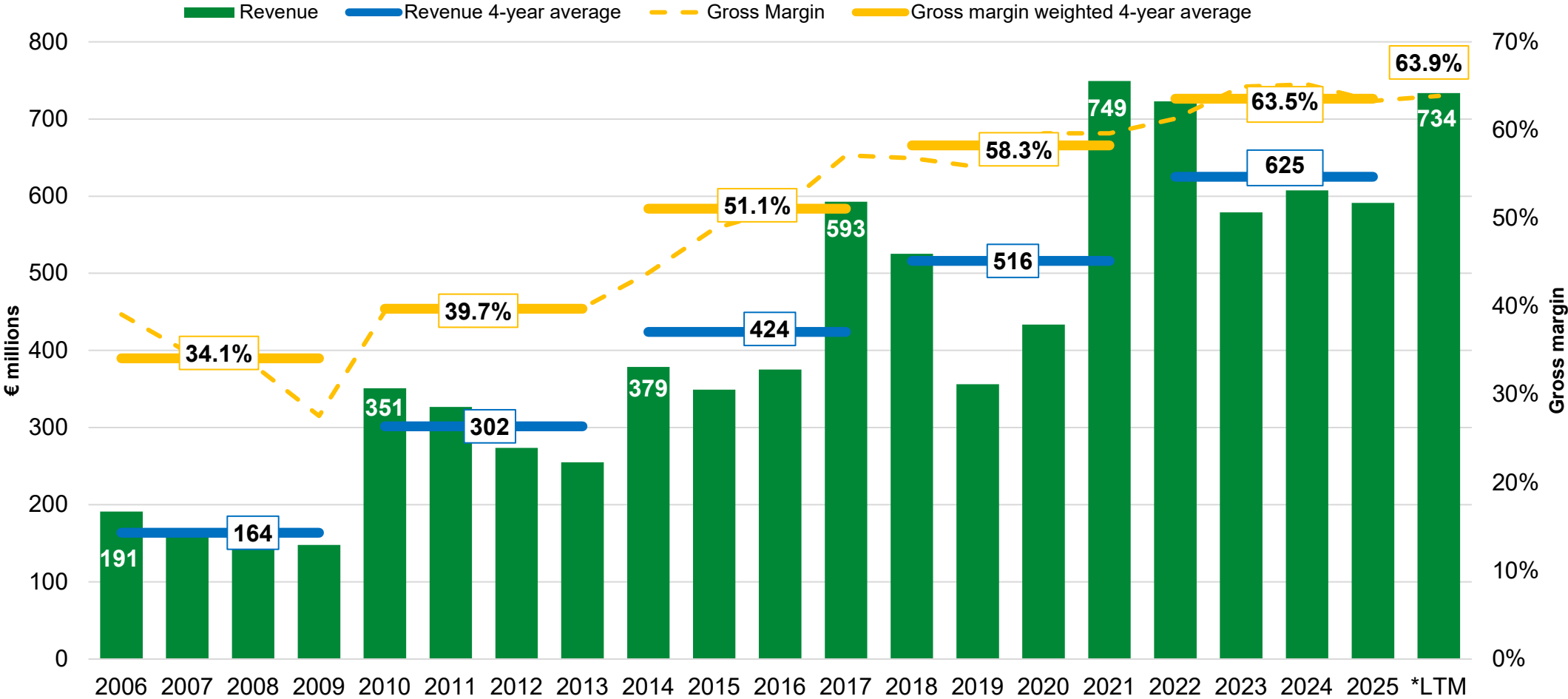
- 2025 gross spending up 11.4% vs. 2024
- New product introductions in 2025-2026 expected to accelerate growth and increase market share

Favorably positioned in highest growth segments: Datacenters, Photonics, AI PCs, Mobile, EV/autonomous driving



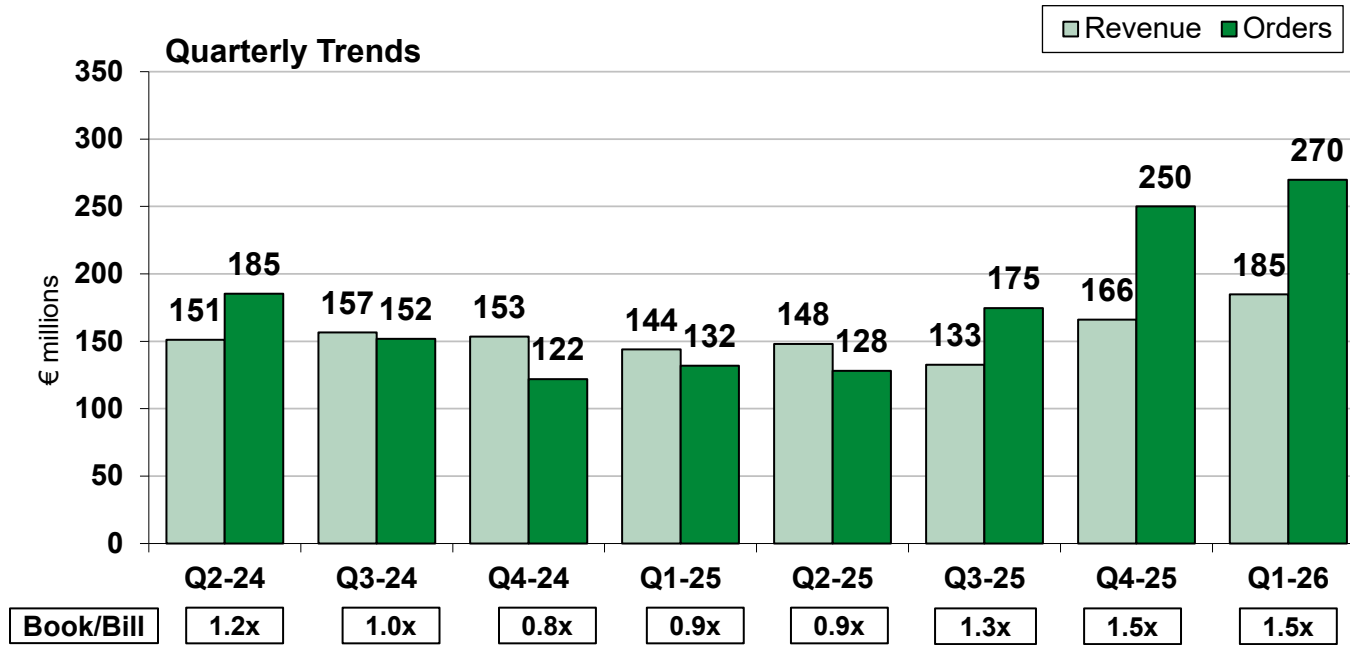
IV. FINANCIAL UPDATE AND SUMMARY

Higher Through Cycle Revenue and Gross Margin Trends



* At midpoint of Q2-26 guidance

Revenue/Order Trends



Q1-26 vs. Q4-25

- **Revenue: +€ 18.5 million (+11.1%)**
 - Above midpoint of guidance
 - Higher mobile, 2.5D AI-related computing and photonics
 - Partial offset: lower automotive revenue
- **Orders: +€ 19.3 million (+7.7%)**
 - Strong hybrid bonding growth

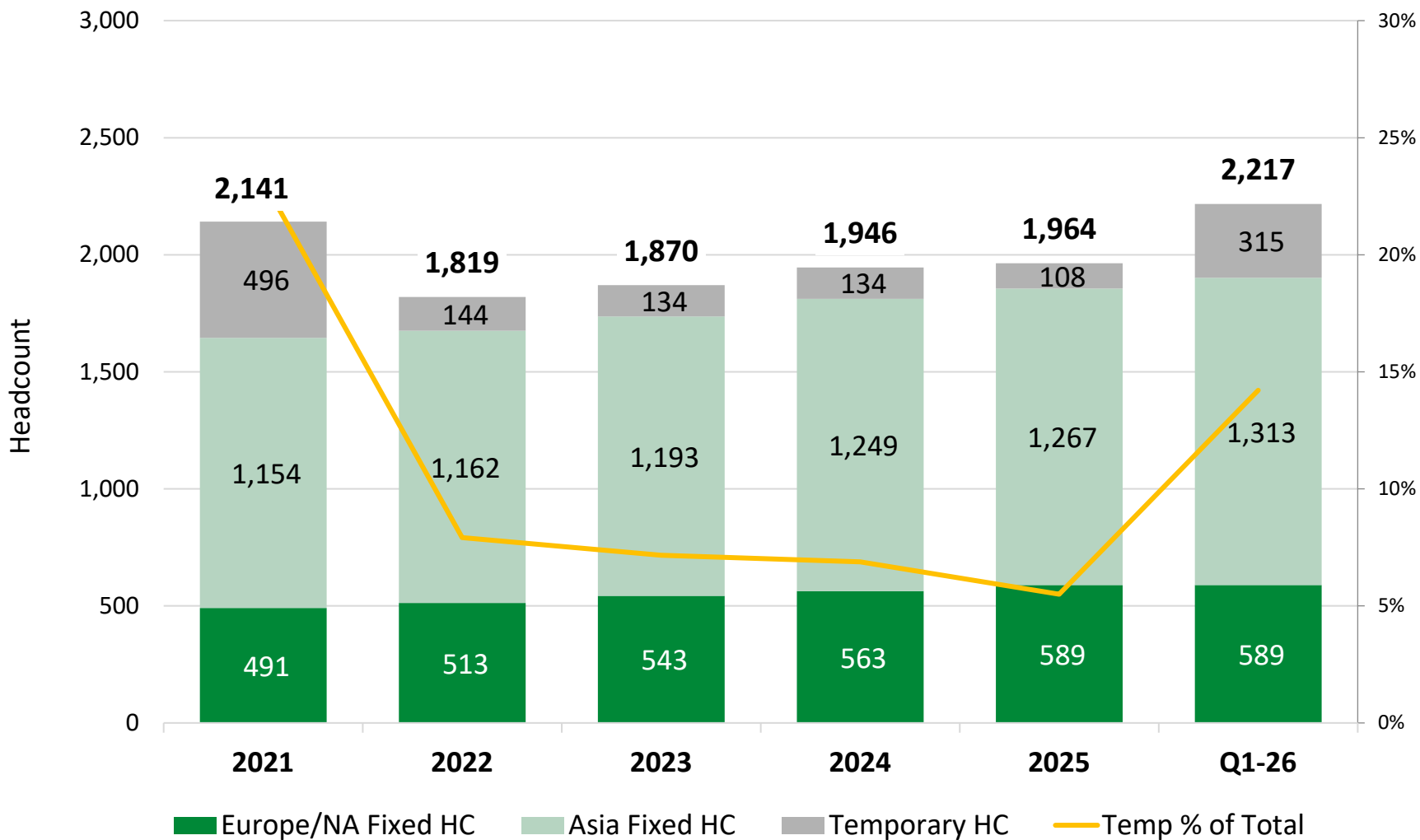
Q1-26 vs. Q1-25

- **Revenue: +€ 40.8 million (+28.3%)**
- **Orders: +€ 137.8 million (+104.5%)**
 - Growth across all end user markets
 - Particular strength in hybrid bonding, mobile and photonics applications

FY-25 vs. FY-24

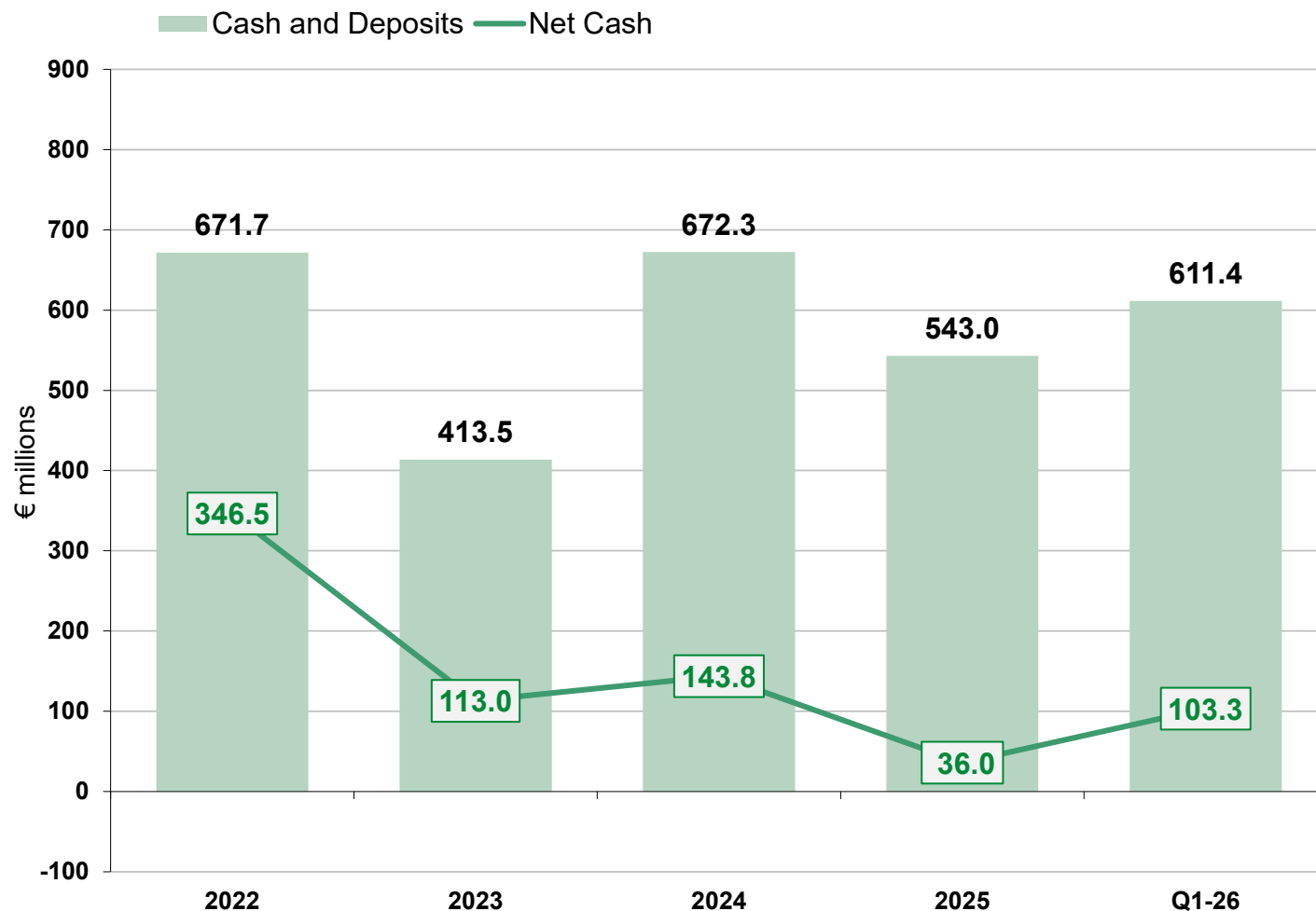
- **Revenue: -€ 16.2 million (-2.7%)**
 - Ongoing weakness in mainstream mobile, automotive and industrial end-user markets
 - Partial offset: Growth by Asian subcons for datacenter and photonics applications
- **Orders: +€ 98.3 million (+16.8%)**
 - Increased orders for AI-related computing applications
 - Renewed capacity purchases for photonics applications

Headcount Trends



Increasing Asian fixed and temporary headcount to support order upturn and increased hybrid bonding activities

Strong Liquidity Position Maintained. Net Cash Position Improving



Q1-26 vs. Q4-25

- Cash and deposits of € 611.4 million
 - + € 68.4 million primarily due to:
 - + € 93.0 million cash flow from operations
 - - € 14.2 million share repurchases
 - - € 6.8 million capex and capitalized R&D
- Net cash of € 103.3 million
 - + € 67.3 million sequentially

Capital Allocation

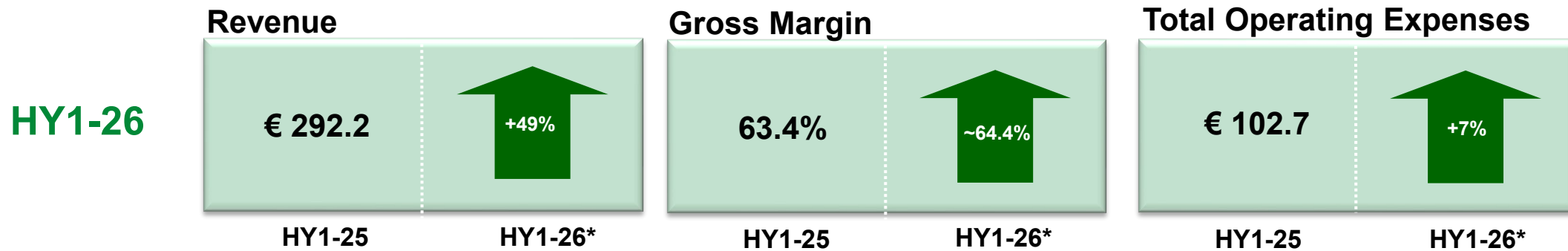
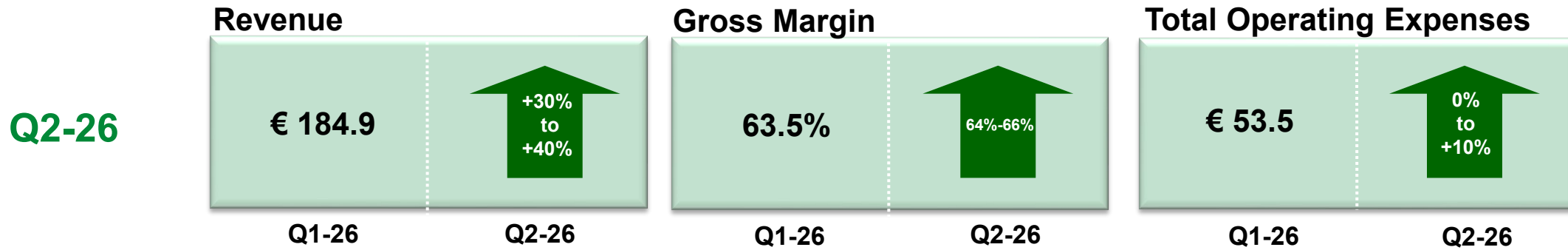
- Capital allocation of € 254.8 million vs. € 251.3 million in 2024
- New € 60 million share repurchase program began in October

Debt Outstanding

- € 175 million 1.875% Convertible Notes due 2029
- € 350 million 4.5% Senior Notes due 2031

Guidance Q2-26 & H1-26

€ in millions



* At midpoint of Q2-26 guidance

**Assembly market
ever more critical in
semiconductor value
chain**

**Disciplined strategic
focus has created an
industry leader**

**Long term secular
trends drive
advanced packaging
growth**

**Wafer level assembly
for AI applications
promising new
growth opportunity**

**Market presence has
grown via key IDMs,
supply chains and
partners**

**Tech leadership and
scalability result in
superior financial
returns**

**Commitment to
sustainable growth
and fighting climate
change**

**Attractive capital
allocation policy**